PMIC FOR E Ink® Vizplex™ ENABLED ELECTRONIC PAPER DISPLAY

Check for Samples: TPS65180, TPS65181, TPS65180B, TPS65181B

FEATURES

- **Single Chip Power Management Solution for E Ink® Vizplex™ Electronic Paper Displays**
- **Generates Positive and Negative Gate and Source Driver Voltages and Back-Plane Bias from a Single, Low-Voltage Input Supply**
- **3-V to 6-V Input Voltage Range**
- **Boost Converter for Positive Rail Base**
- **Inverting Buck-Boost Converter for Negative Rail Base**
- **Two Adjustable LDOs for Source Driver Supply**
  - **LDO1: 15 V, 120 mA (VPOS)**
  - **LDO2: –15 V, 120 mA (VNEG)**
- **Accurate Output Voltage Tracking**
  - **VPOS - VNEG = ±50 mV**
- **Two Charge Pumps for Gate Driver Supply**
  - **CP1: 22 V, 10 mA (VDDH)**
  - **CP2: –20 V, 12 mA, (VEE)**
- **Adjustable VCOM Driver for Accurate Panel-Backplane Biasing**
  - **–0.3 V to –2.5 V**
  - **±1.5% Accuracy (±18 mV)**
  - **8-Bit Control (11-mV Nominal Step Size)**
  - **15-mA Max Integrated Switch**
- **Integrated 3.3-V Power Switch for Disabling System Power Rail**
- **Thermistor Monitoring**
  - **–10°C to 85°C Temperature Range**
  - **±1°C Accuracy from 0°C to 50°C**
- **I^2C Serial Interface**
  - **Slave Address 0x48h (1001000)**
- **Flexible Power-Up Sequencing**
- **Interrupt and Sleep Mode Support**
- **Thermally Enhanced Package for Efficient Heat Management (48-Pin 7 mm x 7 mm x 0.9 mm QFN)**

APPLICATIONS

- **Power Supply for Active Matrix E Ink® Vizplex™ Panels**
- **EPD Power Supply**
- **E-Book Readers**
- **EPSON® S1D13522 (ISIS) Timing Controller**
- **EPSON® S1D13521 (Broadsheet) Timing Controller**
- **Application Processors With Integrated or Software Timing Controller (OMAP™)**

DESCRIPTION

The TPS65180/TPS65181 and TPS65180B/TPS65181B family of devices are single-chip power supplies designed to for E Ink® Vizplex™ displays used in portable e-reader applications and support panel sizes up to 9.7 inches. Two high efficiency DC/DC boost converters generate ±17-V rails which are boosted to 22 V and –20 V by two change pumps to provide the gate driver supply for the Vizplex™ panel. Two tracking LDOs create the ±15-V source driver supplies which support up to 120-mA of output current. All rails are adjustable through the I^2C interface to accommodate specific panel requirements.

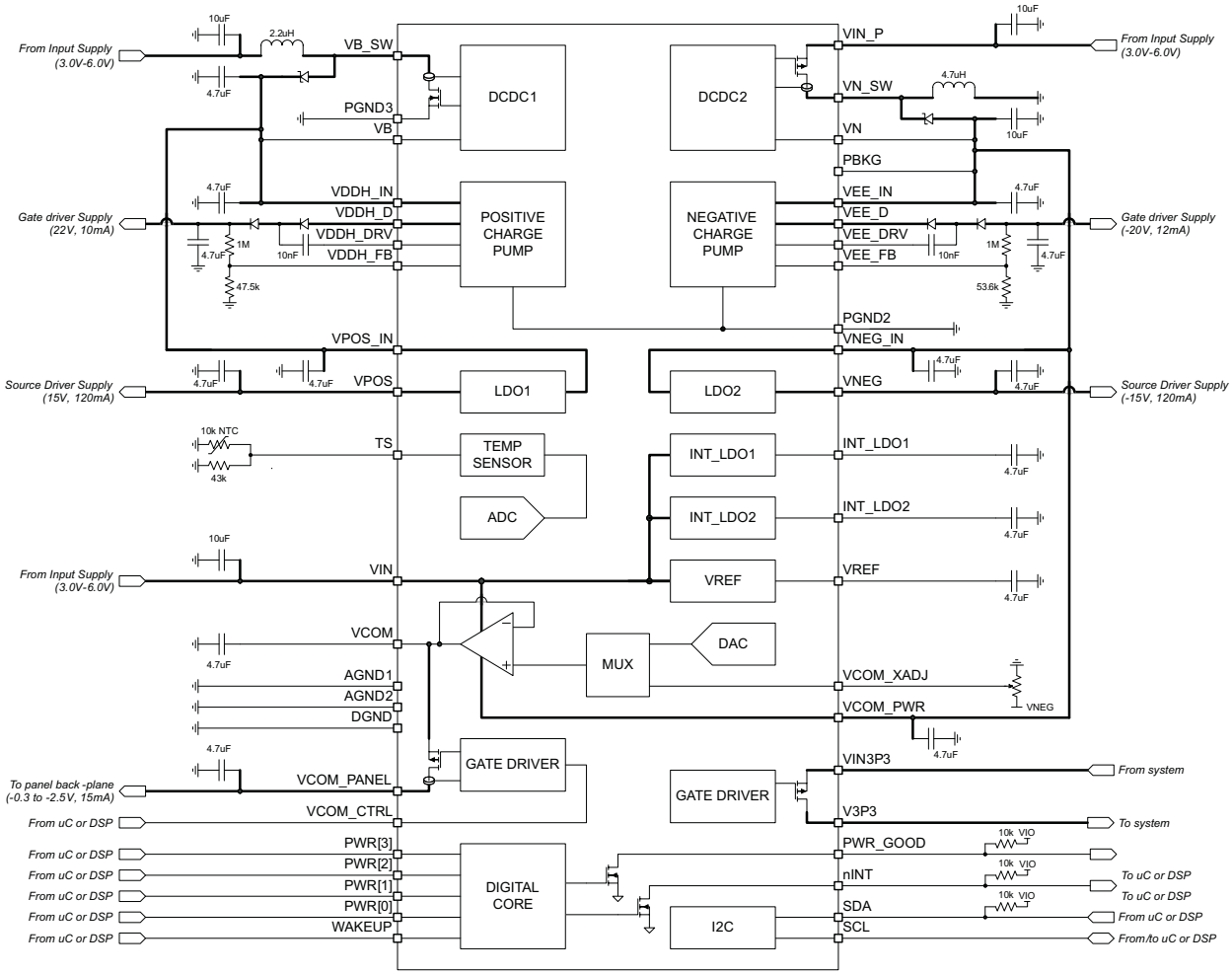
Accurate back-plane biasing is provided by a linear amplifier and can be adjusted either by an external resistor or the I^2C interface. The VCOM driver can source or sink current depending on panel condition. For automatic VCOM adjustment in production line, VCOM can be set from –0.3 V to –2.5 V with 8-bit control through the serial interface. The power switch is integrated to isolate VCOM driver from E Ink® panel.

The TPS65180/TPS65181 and TPS65180B/TPS65181B devices provide precise temperature measurement function to monitor the panel temperature during operation. The TPS65180/TPS65180B requires the host processor to trigger the temperature acquisition through an I^2C write whereas the TPS65181/TPS65181B automatically updates the temperature every 60 s.

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

FUNCTIONAL BLOCK DIAGRAM



ORDERING INFORMATION(1)

T_A	PACKAGE(2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-10°C to 85°C	RGZ	TPS65180RGZR	TPS65180
		TPS65181RGZR	TPS65181
		TPS65180BRGZR	TPS65180B
		TPS65180BRGZR	TPS65181B

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

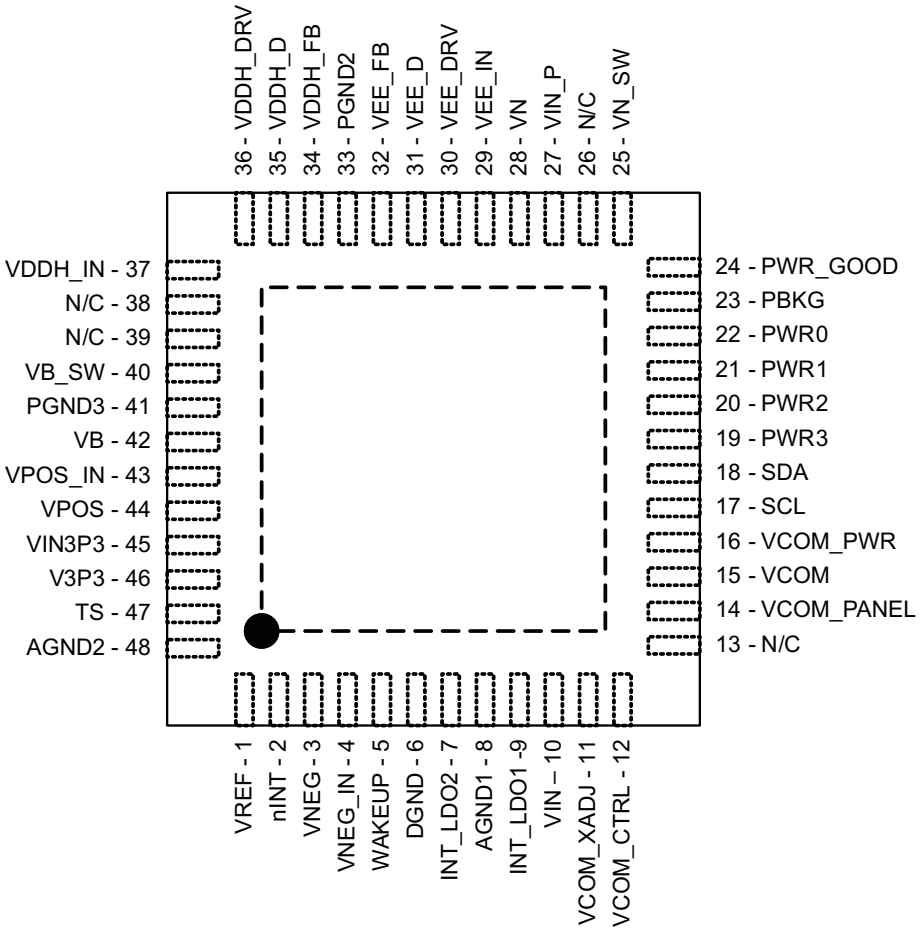
SELECTION GUIDE

DEVICE	PART NUMBER	STATUS
TPS65180	TPS65180RGZR	Not recommended for new designs
TPS65181	TPS65181RGZR	Not recommended for new designs
TPS65180B	TPS65180BRGZR	Active
TPS65181B	TPS65180BRGZR	Active

FUCNTION	TPS65180/TPS65180B	TPS65181/TPS65181B
Compatilbility	EPSON ISIS (S1D113522)	EPSON ISIS (S1D113522)
		EPSON Broadsheet (S1D13521)
	OMAP	OMAP
	ST	ST
Temperature sensor	Triggered by host	Automatically triggers every 60 s
I^2C interface	Standard	Supports standard and Broadsheet protocol
Fault recovery	INT register must be read before rails can be re-enabled after a fault	Interrupts are automatically reset when faults clear. No need to read INT register.
VCOM adjust default	I^2C control	External potentiometer

DEVICE INFORMATION

RGZ PACKAGE
(TOP VIEW)



TERMINAL FUNCTIONS(1)

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
VREF	1	O	Filter pin for 2.25-V internal reference to ADC
nINT	2	O	Open drain interrupt pin (active low)
VNEG	3	O	Negative supply output pin for panel source drivers
VNEG_IN	4	I	Input pin for LDO2 (VNEG)
WAKEUP	5	I	Wake up pin (active high). Pull this pin high to wake up from sleep mode.
DGND	6		Digital ground
INT_LDO2	7	O	Internal supply (digital circuitry) filter pin
AGND1	8		Analog ground for general analog circuitry
INT_LDO1	9	O	Internal supply (analog circuitry) filter pin
VIN	10	I	Input power supply to general circuitry
VCOM_XADJ	11	I	Analog input for conventional VCOM setup method. Tie this pin to ground if VCOM is set through I^2C interface.
VCOM_CTRL	12	I	VCOM_PANEL gate driver enable (active high)
N/C	13		Not connected

(1) There will be 0-ns, 93.75-µs, 62.52-µs of deglitch for PWRx, WAKEUP, and VCOM_CTRL, respectively.

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
VCOM_PANEL	14	O	Panel common-voltage output pin
VCOM	15	O	Filter pin for panel common-voltage driver
VCOM_PWR	16	I	Internal supply input pin to VCOM buffer. Connect to the output of DCDC2.
SCL	17	I	Serial interface (I^2C) clock input
SDA	18	I/O	Serial interface (I^2C) data input/output
PWR3	19	I	Enable pin for CP1 (VDDH) (active high)
PWR2	20	I	Enable pin for LDO1 (VPOS) (active high)
PWR1	21	I	Enable pin for CP2 (VEE) (active high)
PWR0	22	I	Enable pin for LDO2 (VNEG) and VCOM (active high)
PWR_GOOD	24	O	Open drain power good output pin (active low)
VN_SW	25	O	Inverting buck-boost converter switch out (DCDC2)
N/C	26		Not connected
VIN_P	27	I	Input power supply to inverting buck-boost converter (DCDC2)
VN	28	I	Feedback pin for inverting buck-boost converter (DCDC2)
VEE_IN	29	I	Input supply pin for CP1 (VEE)
VEE_DRV	30	O	Driver output pin for negative charge pump (CP2)
VEE_D	31	O	Base voltage output pin for negative charge pump (CP2)
VEE_FB	32	I	Feedback pin for negative charge pump (CP2)
PGND2	33		Power ground for CP1 (VDDH) and CP2 (VEE) charge pumps
VDDH_FB	34	I	Feedback pin for positive charge pump (CP1)
VDDH_D	35	O	Base voltage output pin for positive charge pump (CP1)
VDDH_DRV	36	O	Driver output pin for positive charge pump (CP1)
VDDH_IN	37	I	Input supply pin for positive charge pump (CP1)
N/C	38		Not connected
N/C	39		Not connected
VB_SW	40	O	Boost converter switch out (DCDC1)
PGND3	41		Power ground for DCDC1
VB	42	I	Feedback pin for boost converter (DCDC1)
VPOS_IN	43	I	Input pin for LDO1 (VPOS)
VPOS	44	O	Positive supply output pin for panel source drivers
VIN3P3	45	I	Input pin to 3.3-V power switch
V3P3	46	O	Output pin of 3.3-V power switch
TS	47	I	Thermistor input pin. Connect a 10k NTC thermistor and a 43k linearization resistor between this pin and AGND2.
AGND2	48		Reference point to external thermistor and linearization resistor
PowerPad (PBKG)	23		Die substrate/thermal pad. Connect to VN with short, wide trace. Wide copper trace will improve heat dissipation. PowerPad must not be connected to ground.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) (1)(2)

			VALUE	UNIT
	Input voltage range at VIN, VINP, VIN3P3		–0.3 to 7	V
	Ground pins to system ground		–0.3 to 0.3	V
	Voltage range at SDA, SCL, WAKEUP, PWR3, PWR2, PWR1, PWR0, VCOM_CTRL, VDDH_FB, VEE_FB, PWR_GOOD, nINT		–0.3 to 3.6	V
	VCOM_XADJ		–3.6 to 0.3	V
	Voltage on VB, VB_SW, VPOS_IN, VDDH_IN		–0.3 to 20	V
	Voltage on VN, VNEG_IN, VEE_IN, VCOM_PWR		–20 to 0.3	V
	Voltage from VINP to VN_SW		–0.3 to 30	V
	Peak output current		Internally limited	mA
	Continuous total power dissipation		2	W
θ_{JA}	Junction-to-ambient thermal resistance(3)		23	°C/W
T_J	Operating junction temperature		-10 to 125	°C
T_A	Operating ambient temperature(4)		-10 to 85	°C
T_{stg}	Storage temperature		-65 to 150	°C
	ESD rating	(HBM) Human body model	±2000	V
		(CDM) Charged device model	±500	

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to network ground terminal.
(3) Estimated when mounted on high K JEDEC board per JESD 51-7 with thickness of 1.6 mm, 4 layers, size of 76.2 mm X 114.3 mm, and 2 oz. copper for top and bottom plane. Actual thermal impedance will depend on PCB used in the application.
(4) It is recommended that copper plane in proper size on board be in contact with die thermal pad to dissipate heat efficiently. Thermal pad is electrically connected to PBKG, which is supposed to be tied to the output of buck-boost converter. Thus wide copper trace in the buck-boost output will help heat dissipated efficiently.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
	Input voltage range at VIN, VINP, VIN3P3	3	3.7	6	V
	Voltage range at SDA, SCL, WAKEUP, PWR3, PWR2, PWR1, PWR0, VCOM_CTRL, VDDH_FB, VEE_FB, VCOM_XADJ, PWR_GOOD, nINT	0		3.6	V
T_A	Operating ambient temperature range	–10		85	°C
T_J	Operating junction temperature range	–10		125	°C

RECOMMENDED EXTERNAL COMPONENTS

PART NUMBER	VALUE	SIZE	MANUFACTURER
INDUCTORS			
LQH44PN4R7MP0	4.7 µH	4 mm x 4 mm x 1.65 mm	Murata
VLS252012T-2R2M1R3	2.2 µH	2 mm x 2.5 mm x 1.2 mm	TDK
CAPACITORS			
GRM21BC81E475KA12L	4.7 µF, 25 V, X6S	805	Murata
GRM32ER71H475KA88L	4.7 µF, 50 V, X7R	1210	Murata
All other caps	X5R or better		
DIODES			
BAS3010		SOD-323	Infineon
MBR130T1		SOD-123	ON-Semi
THERMISTOR			
NCP18XH103F03RB	10 kW	603	Murata

ELECTRICAL CHARACTERISTICS

V_{IN} = 3.7 V, T_A = –10°C to 85ºC, Typical values are at T_A = 25ºC (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT VOLTAGE						
V_{IN}	Input voltage range		3	3.7	6	V
V_{UVLO}	Undervoltage lockout threshold	V_{IN} falling		2.9		V
V_{HYS}	Undervoltage lockout hysteresis	V_{IN} rising		400		mV
INPUT CURRENT						
I_Q	Operating quiescent current into VIN	Device switching, no load		5.5		mA
I_{STD}	Operating quiescent current into VIN	Device in standby mode		130		µA
I_{SLEEP}	Shutdown current	Device in sleep mode		2.8	10	µA
INTERNAL SUPPLIES						
VI_{NT_LDO1}	Internal supply			2.7		V
V_{INT_LDO2}	Internal supply			2.7		V
V_{REF}	Internal supply			2.25		V
DCDC1 (POSITIVE BOOST REGULATOR)						
V_{IN}	Input voltage range		3	3.7	6	V
V_{OUT}	Output voltage range			17		V
	DC set tolerance		-5		5	%
I_{OUT}	Output current				160	mA
$R_{DS(ON)}$	MOSFET on resistance	V_{IN} = 3.7 V		350		mΩ
I_{LIMIT}	Switch current limit			1.5		A
	Switch current accuracy		-30		30	%
f_{SW}	Switching frequency			1		MHz
L	Inductor			2.2		µH
C	Capacitor			2x4.7		µF
ESR	Capacitor ESR			20		mΩ
DCDC2 (INVERTING BUCK-BOOST REGULATOR)						
V_{IN}	Input voltage range		3	3.7	6	V
V_{OUT}	Output voltage range			-17		V
	DC set tolerance		-5		5	%
I_{OUT}	Output current				160	mA
$R_{DS(ON)}$	MOSFET on resistance	V_{IN} = 3.7 V		350		mΩ
I_{LIMIT}	Switch current limit			1.5		A
	Switch current accuracy		-30		30	%
L	Inductor			4.7		µH
C	Capacitor			2x4.7		µF
ESR	Capacitor ESR			20		mΩ
LDO1 (VPOS)						
V_{POS_IN}	Input voltage range		16.15	17	17.85	V
V_{SET}	Output voltage set value	V_{IN} = 17 V, $V_{POS\_SET[2:0]}$ = 0x0h to 0x7h	14.25	15	15.75	V
$V_{INTERVAL}$	Output voltage set resolution	V_{IN} = 17 V		250		mV
V_{POS_OUT}	Output voltage range	V_{SET} = 15 V, I_{LOAD} = 20 mA	14.85	15	15.15	V
V_{OUTTOL}	Output tolerance	V_{SET} = 15 V, I_{LOAD} = 20 mA	-1		1	%
$V_{DROPOUT}$	Dropout voltage	I_{LOAD} = 120 mA			250	mV
$V_{LOADREG}$	Load regulation – DC	I_{LOAD} = 10% to 90%			1	%
I_{LOAD}	Load current range			120		mA

ELECTRICAL CHARACTERISTICS (continued)

V_{IN} = 3.7 V, T_A = –10°C to 85ºC, Typical values are at T_A = 25ºC (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{LIMIT}	Output current limit		200			mA
T_{SS}	Soft start time			1		ms
C	Recommended output capacitor			4.7		µF
LDO2 (VNEG)						
V_{NEG_IN}	Input voltage range		-17.85	-17	-16.15	V
V_{SET}	Output voltage set value	V_{IN} = –17 V, $V_{NEG\_SET[2:0]}$ = 0x0h to 0x7h	-15.75	-15	-14.25	V
$V_{INTERVAL}$	Output voltage set resolution	V_{IN} = –17 V		250		mV
V_{NEG_OUT}	Output voltage range	V_{SET} = –15 V, I_{LOAD} = –20 mA	-15.15	-15	-14.85	V
V_{OUTTOL}	Output tolerance	V_{SET} = –15 V, I_{LOAD} = –20 mA	-1		1	%
$V_{DROPOUT}$	Dropout voltage	I_{LOAD} = 120 mA			250	mV
$V_{LOADREG}$	Load regulation – DC	I_{LOAD} = 10% to 90%			1	%
I_{LOAD}	Load current range			120		mA
I_{LIMIT}	Output current limit		200			mA
T_{SS}	Soft start time			1		ms
C	Recommended output capacitor			4.7		µF
LD01 (POS) AND LDO2 (VNEG) TRACKING						
V_{DIFF}	Difference between VPOS and VNEG	V_{SET} = ±15 V, I_{LOAD} = ±20 mA, 0°C to 60°C	-50		50	mV
VCOM DRIVER						
V_{COM}	Accuracy	$V_{COM\_SET[7:0]}$ = 0x74h (–1.25 V) V_{IN} = 3.4 V to 4.2 V, no load	-0.8		0.8	%
		$V_{COM\_SET[7:0]}$ = 0x74h (–1.25 V) V_{IN} = 3.0 V to 6.0 V, no load	-1.5		1.5	
	Output voltage range		-2.5		-0.3	V
	Resolution	V_{COM_ADJ} = 1 V, 1 LSB		11	17	mV
G	V_{COM} gain (V_{COM_XADJ}/V_{COM})	V_{COM_ADJ} = 0 V		1		V/V
VCOM SWITCH						
T_{ON}	Switch ON time	V_{COM} = –1.25 V, V_{COM_PANEL} = 0 V C_{VCOM} = 4.7 µF, C_{VCOM_PANEL} = 4.7 µF			1	ms
$R_{DS(ON)}$	MOSFET ON resistance	V_{COM} = –1.245 V, I_{COM} = 30 mA		20	35	Ω
I_{LIMIT}	MOSFET current limit	Not tested in production		200		mA
I_{SWLEAK}	Switch leakage current	V_{COM} = 0 V, V_{COM_PANEL} = –2.5 V			8.3	nA
VIN3P3 TO V3P3 SWITCH						
$R_{DS(ON)}$	MOSFET ON resistance	V_{IN3P3} = 3.3 V, I_D = 2 mA		50		Ω
CP1 (VDDH) CHARGE PUMP						
V_{DDH_IN}	Input voltage range		16.15	17	17.85	V
V_{FB}	Feedback voltage			1		V
	Accuracy		-3		3	%
V_{DDH_OUT}	Output voltage range	V_{SET} = 22 V, I_{LOAD} = 2 mA	21	22	23	V
I_{LOAD}	Load current range				10	mA
f_{SW}	Switching frequency			560		KHz
C_D	Recommended driver capacitor			10		nF
C_O	Recommended output capacitor			4.7		µF
CP2 (VEE) NEGATIVE CHARGE PUMP						
V_{EE_IN}	Input voltage range		-17.75	-17	-16.15	V

ELECTRICAL CHARACTERISTICS (continued)

V_{IN} = 3.7 V, T_A = –10°C to 85ºC, Typical values are at T_A = 25ºC (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{FB}	Feedback voltage			-1		V
	Accuracy		-3		3	%
V_{EE_OUT}	Output voltage range	V_{SET} = –20 V, I_{LOAD} = 3 mA	-21	-20	-19	V
I_{LOAD}	Load current range				12	mA
f_{SW}	Switching frequency			560		KHz
C_D	Recommended driver capacitor			10		nF
C_O	Recommended output capacitor			4.7		µF
THERMISTOR MONITOR(1)						
A_{TMS}	Temperature to voltage ratio	Not tested in production		-0.0158		V/°C
$Offset_{TMS}$	Offset	Temperature = 0°C		1.575		V
V_{TMS_HOT}	Temp hot trip voltage (T = 50°C)	TEMP_HOT_SET = 0x8C		0.768		V
V_{TMS_COOL}	Temp hot escape voltage (T = 45°C)	TEMP_COOL_SET = 0x82		0.845		V
V_{TMS_MAX}	Maximum input level			2.25		V
R_{NTC_PU}	Internal pull up resistor			7.307		KΩ
R_{LINEAR}	External linearization resistor			43		KΩ
ADC_{RES}	ADC resolution	Not tested in production, 1 bit		8.75		mV
ADC_{DEL}	ADC conversion time	Not tested in production		19		µs
$TMST_{TOL}$	Accuracy	Not tested in production	-2		2	LSB
LOGIC LEVELS AND TIMING CHARTERISTICS (SCL, SDA, nINT, PWR_GOOD, PWRx, WAKEUP)						
V_{OL}	Output low threshold level	I_O = 3 mA, sink current (SDA, nINT, PWR_GOOD)			0.4	V
V_{IL}	Input low threshold level				0.4	V
V_{IH}	Input high threshold level		1.2			V
$I_{(bias)}$	Input bias current	V_{IO} = 1.8 V			1	µA
$t_{low,WAKEUP}$	WAKEUP low time	minimum low time for WAKEUP pin	150			ms
f_{SCL}	SCL clock frequency				400	KHz
OSCILLATOR						
f_{OSC}	Oscillator frequency			9		MHz
	Frequency accuracy	T_A = –40°C to 85°C	-10		10	%
THERMAL SHUTDOWN						
T_{SHTDWN}	Thermal trip point			150		°C
	Thermal hysteresis			20		°C

(1) 10-kΩ Murata NCP18XH103F03RB thermistor (1%) in parallel with a linearization resistor (43kΩ, 1%) are used at TS pin for panel temperature measurement.

MODES OF OPERATION

The TPS65180/TPS65181 and TPS65180B/TPS65181B have three modes of operation, SLEEP, STANDBY, and ACTIVE. SLEEP mode is the lowest-power mode in which all internal circuitry is turned off. In STANDBY, all power rails are shut down but the device is ready to accept commands through PWR[3:0] pins and/or I^2C interface. In ACTIVE mode one or more power rails are enabled.

SLEEP

This is the lowest power mode of operation. All internal circuitry is turned off, registers are reset to default values and the device does not respond to I^2C communications. TPS65180/TPS65181 and TPS65180B/TPS65181B enter SLEEP mode whenever WAKEUP pin is pulled low.

STANDBY

In STANDBY all internal support circuitry is powered up and the device is ready to accept commands either through GPIO or I^2C control but none of the power rails are enabled. To enter STANDBY mode the WAKEUP pin must be pulled high and all PWRx pins must be pulled low or the STANDBY bit of the ENABLE register must be set high. The device also enters STANDBY mode if input under voltage lock out (UVLO), positive boost under voltage (VB_UV), or inverting buck-boost under voltage (VN_UV) is detected, or thermal shutdown occurs.

ACTIVE

The device is in ACTIVE mode when any of the output rails are enabled and no fault condition is present. This is the normal mode of operation while the device is powered up. In ACTIVE mode, a falling edge on any PWRx pin shuts down and a rising edge powers up the corresponding rail.

MODE TRANSISITONS

SLEEP → ACTIVE

WAKEUP pin is pulled high (rising edge) with any PWRx pin high. Rails come up in the order defined by the PWR_SEQx registers.

SLEEP → STANDBY

WAKEUP pin is pulled high (rising edge) with all PWRx pins low. Rails will remain down until one or more PWRx pin is pulled high.

ACTIVE → SLEEP

WAKEUP pin is pulled low (falling edge). Rails are shut down in the reverse power-up order defined by PWR_SEQ registers.

ACTIVE → STANDBY

WAKEUP pin is high. All PWRx pins are pulled low (falling edge). Rails shut down in the order in which PWRx pins are pulled low. In the event of thermal shut down (TSD), under voltage lock out (UVLO), positive boost or inverting buck-boost under voltage (UV), or when STANDBY bit is set to 1, the device shuts down all rails in the reverse power-up order defined by the PWR_SEQx registers.

STANDBY → ACTIVE

WAKEUP pin is high and any PWRx pin is pulled high (rising edge). Rails come up in the same order as PWRx pins are pulled high. Alternatively, if ACTIVE bit is set to 1, output rails will power up in the order defined by the PWR_SEQx registers.

STANDBY → SLEEP

WAKEUP pin is pulled low (falling edge) while none of the output rails are enabled.

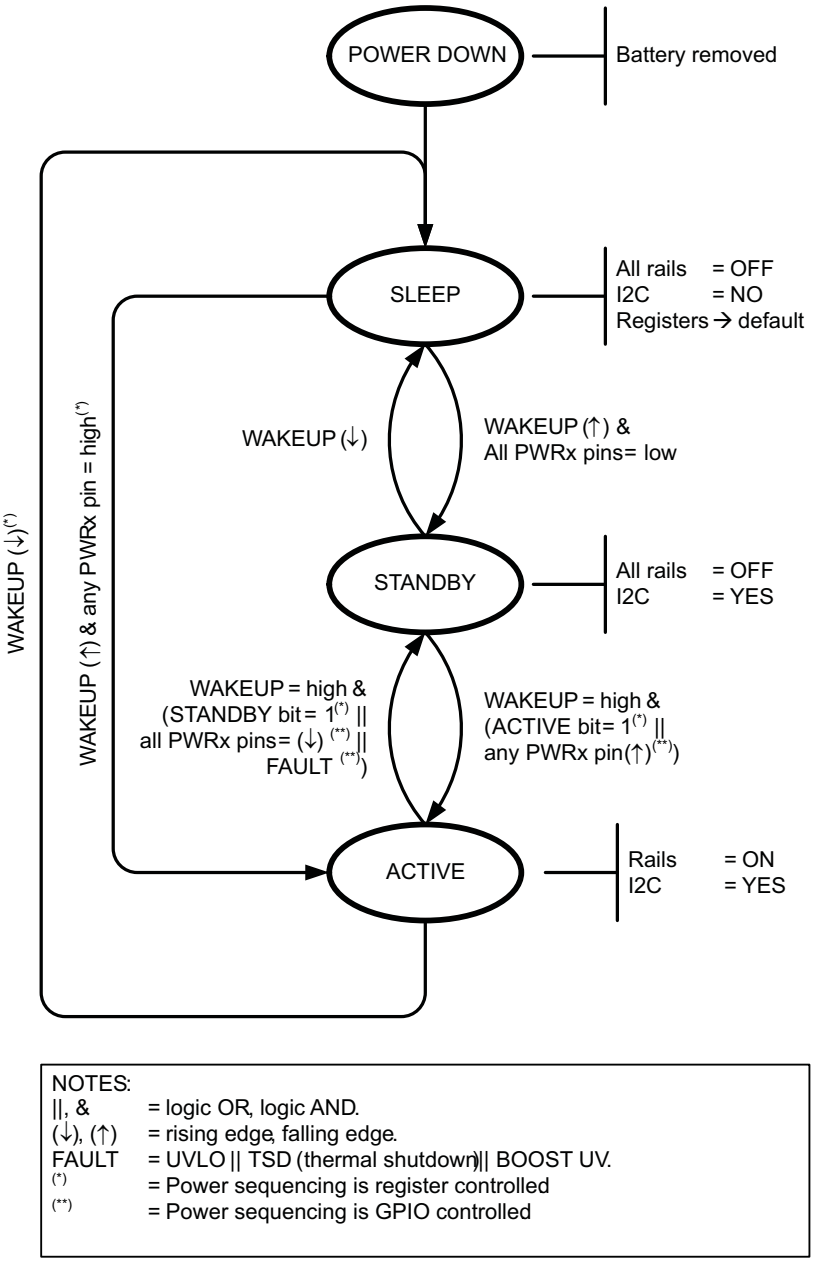


Figure 1. Global State Diagram

WAKE-UP AND POWER UP SEQUENCING

The TPS65180/TPS65181 and TPS65180B/TPS65181B support flexible power-up sequencing through GPIO control using the PWR3, 2, 1, 0 pins or I^2C control using the PWR_SEQ0, 1, 2 registers. Using GPIO control, the output rails are enabled/disabled in the order in which the PWRx pins are asserted/de-asserted, respectively, and the power-up timing is controlled by the host only.

In I^2C control mode the power-up/down order and timing are defined by user register settings. The default settings support the E Ink® Vizplex™ panel and typically do not need to be charged by the user.

GPIO CONTROL

Under GPIO control the system host in E Ink® Vizplex™ panel module enables the TPS65180/TPS65181 and TPS65180B/TPS65181B output rails by asserting the PWR0, PWR1, PWR2, PWR3 signals and the host has full control over the order and timing in which the output rails are powered up and down. Rails are in regulation 2 ms after their respective PWRx pin has been asserted with the exception of the first rail, which takes 6 ms to power up. The additional time is needed to power up the positive and inverting buck-boost regulator which need to be turned on before any other rail can be enabled. Once all rails are enabled and in regulation the PWR_GOOD pin is released (pin status = HiZ and power good line is pulled high by external pull-up resistor). The PWRx pins are assigned to the rails as follows:

- PWR0: LDO2 (VNEG) and VCOM
- PWR1: CP2 (VEE)
- PWR2: LDO2 (VPOS)
- PWR3: CP1 (VDDH)

Rails are powered down whenever the host de-asserts the respective PWRx pin, and once all rails are disabled the device enters STANDBY mode. The next step is then to de-assert the WAKEUP pin to enter SLEEP mode which is the lowest-power mode of operation.

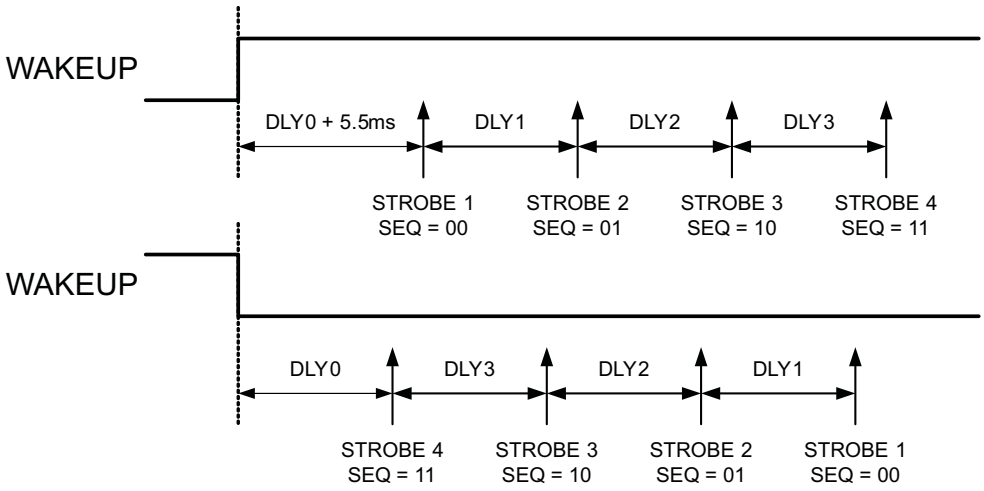
It is possible for the host to force the TPS65180/TPS65181 and TPS65180B/TPS65181B directly into SLEEP mode from ACTIVE mode by de-asserting the WAKEUP pin in which case the device follows the power-down sequence defined by the PWR_SEQx registers before entering SLEEP mode.

I^2C CONTROL

Under I^2C control the power-up sequence is defined by the PWR_SEQx registers rather than through GPIO control. In SLEEP mode the TPS65180/TPS65181 and TPS65180B/TPS65181B are completely turned off, the I^2C registers are reset, and the device does not accept any I^2C transaction. Pull the WAKEUP pin high while all PWRx pins are held low and the device will enter STANDBY mode which enables the I^2C interface. Write to the PWR_SEQ0 register to define the order in which the output rails will be enabled at power-up and to the PWR_SEQ1 and PWR_SEQ2 registers to define the power-up delays between rails. Finally, set the ACTIVE bit in the ENABLE register to 1 to execute the power-up sequence and bring up all power rails.

It is possible for the host to force the TPS65180/TPS65181 and TPS65180B/TPS65181B directly into ACTIVE mode from SLEEP mode by pulling the WAKEUP pin high while at least one of the PWRx pins is pulled high. In this case the default power-up sequence defined by the PWR_SEQx registers applies and the device will start powering up the rails 5.5 ms after the WAKEUP signal has been pulled high.

To power-down the device, set the STANDBY bit of the ENABLE register to 1 then the TPS65180/TPS65181 and TPS65180B/TPS65181B will follow the reverse power-up sequence to bring down all power rails. While the sequencer is busy powering up the power rails, any activity on the PWRx pins is ignored. Once all rails are up, any of the output rails can be disabled by applying a negative edge on the PWRx input pins, i.e. if the host toggles the PWRx pin high-low or low-high-low, the respective rail will be disabled regardless of how it has been enabled.



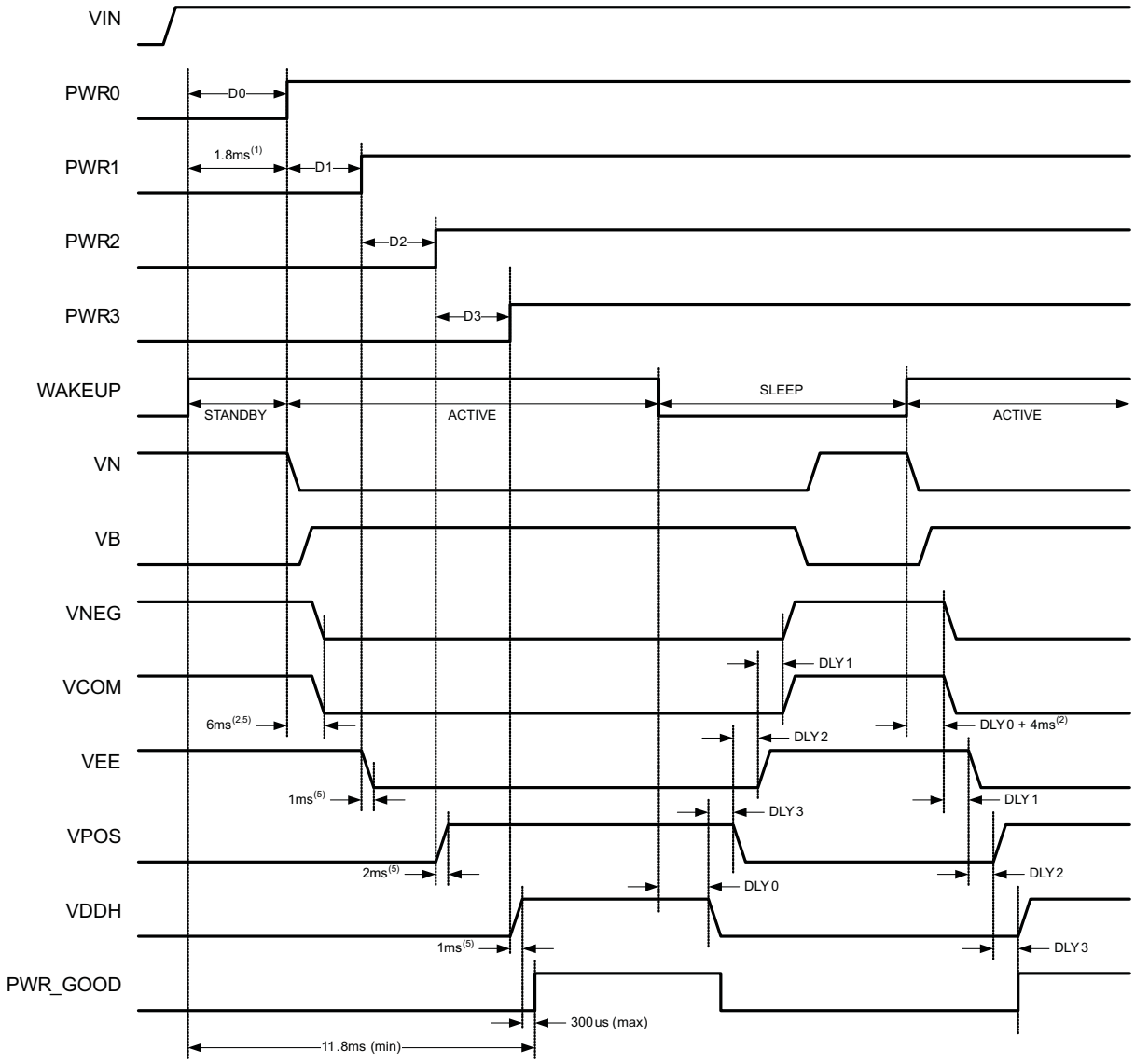
TOP: Power-up sequence is defined by assigning strobes to individual rails. STROBE1 is the first strobe to occur after WAKEUP has been pulled high and STROBE4 is the last event in the sequence. STROBES are assigned to rails in PWR_SEQ0 register and delays between states are defined in PWR_SEQ1 and PWR_SEQ2 registers.
BOTTOM: Power-down sequence follows reverse power-up sequence.

Figure 2. I^2C Control

DEPENDENCIES BETWEEN RAILS

Charge pumps, LDOs, and VCOM driver are dependent on the positive and inverting buck-boost converters and several dependencies exist that affect the power-up sequencing. These dependencies are listed below.

1. Inverting buck-boost (DCDC2) must be in regulation before positive boost (DCDC1) can be enabled. Internally, DCDC1 enable is gated by DCDC2 power good.
2. Positive boost (DCDC1) must be in regulation before LDO2 (VNEG) can be enabled. Internally LDO2 enable is gated DCDC1 power-good.
3. Positive boost (DCDC1) must be in regulation before VCOM can be enabled; Internally VCOM enable is gated by DCDC1 power good.
4. Positive boost (DCDC1) must be in regulation before negative charge pump (CP2) can be enabled. Internally CP2 enable is gated by DCDC1 power good.
5. Positive boost (DCDC1) must be in regulation before positive charge pump (CP1) can be enabled. Internally CP1 enable is gated by DCDC1 power good.
6. LDO2 must be in regulation before LDO1 can be enabled. Internally LDO1 enable is gated by LDO2 power good.
7. The minimum delay time between any two PWRx pins must be > 62.5 µs in order to follow the power up sequence defined by GPIO control. If any two PWRx pins are pulled up together (< 62.5 µs apart) or the sequencer tries to bring up the rails at the same time by assigning the same STROBE to rails in PWR_SEQ0 register, rails will be staggered in a manner that a subsequent rail's enable is gated by PG of a preceding rail. In this case, the default order of power-up is LDO2 (VNEG), CP2 (VEE), LDO1 (VPOS), and CP1(VDDH). If any two PWRx pins are pulled low together or the sequencer tries to bring down the rails at the same time by assigning the same STROBE to rails in PWR_SEQ0 register, then all rails will go down at the same time.



(1) Minimum delay time between WAKEUP rising edge and IC rady to accept I 2C transaction .
(2) It takes 2ms minimum for each internal boost regulator to start up before VNEG can be enabled .
(5) It takes up to 2ms for LDOs (VPOS,VNEG) and 1ms for charge pumps (VDDH,VEE), to reach their steady state after being enabled.
DLY 0-DLY 3 are power up /down delays defined in register PWR _SEQ 1 and PWR_SEQ2.

In this example the first power-up sequence is determined by GPIO control (WAKEUP is pulled high while PWRx pins are low). Power-down and 2nd power-up sequence is controlled by register settings (WAKEUP pin is toggled with at least one PWR pin held high).

Figure 3. Power-Up and Power-Down Timing Diagram

SOFTSTART

Softstart for DCDC1, DCDC2, LDO1, and LDO2 is accomplished by lowering the current limits during start-up. If DCDC1 or DCDC2 are unable to reach power-good status within 10 ms, the corresponding UV flag is set in the interrupt registers, the interrupt pin is pulled low, and the device enters STANDBY mode. LDO1, LDO2, positive and negative charge pumps have a 5ms power-good time-out limit. If either rail is unable to power up within 5 ms after it has been enabled, the corresponding UV flag is set and the interrupt pin is pulled low. However, the device will remain in ACTIVE mode in this case.

VCOM ADJUSTMENT

Through the I²C interface the user can select between two methods of VCOM voltage adjustment:

1. Using the internal 8-bit DAC and register control.
2. Using an external voltage source (resistor divider) connected to the VCOM_XADJ pin.

VCOM ADJUSTMENT THROUGH REGISTER CONTROL

By default the TPS65180/TPS65180B is setup for internal VCOM control through the I²C interface. The default setting for the 8-bit DAC is 0x74h which results in 1.25 V ±0.8% for VCOM. VCOM can be adjusted up or down in steps of 11 mV (typ) by writing to the VCOM_ADJUST register. The output range for VCOM is limited to –0.3 V to –2.5 V.

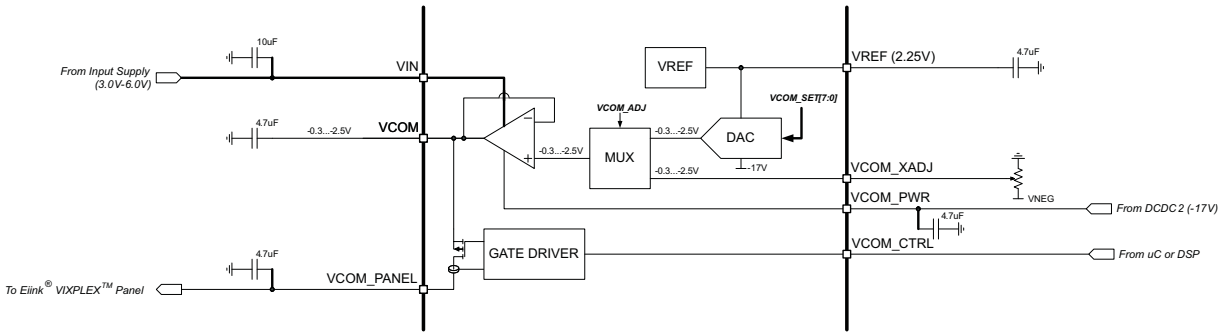


Figure 4. Block Diagram of VCOM Circuit

VCOM ADJUSTMENT THROUGH EXTERNAL POTENTIOMETER

VCOM can be adjusted by an external potentiometer by setting the VCOM_ADJ bit of the VN_ADJUST register to 0 and connecting a potentiometer to the VCOM_XADJ pin. The potentiometer must be connected between ground and a negative supply as shown in Figure 4. The gain from VCOM_XADJ to VCOM is 1 and therefore the voltage applied to VCOM_XADJ pin should range from –0.3 V to –2.5 V.

VPOS / VNEG SUPPLY TRACKING

LDO1 (VPOS) and LDO2 (VNEG) track each other in a way that they are of opposite sign but same magnitude. The sum of VLDO1 and VLOD2 is guaranteed to be < 50 mV. To ensure proper tracking of the supplies the VPOS_SET[2:0] bits of the VP_ADUST register must remain at the default setting of 010b. To adjust the VPOS/VNEG output voltage, write to the VN_ADJUST register only and keep the VPOS_SET[2:0] bits of the VP_ADUST register unchanged.

FAULT HANDLING AND RECOVERY

The TPS65180/TPS65181 and TPS65180B/TPS65181B monitor input and output voltages and die temperature and will take action if operating conditions are outside normal limits. Whenever the TPS65180/TPS65181 and TPS65180B/TPS65181B encounter:

- Thermal Shutdown (TSD)
- Positive Boost Under Voltage (VB_UV)
- Inverting Buck-Boost Under Voltage (VN_UV)
- Input Under Voltage Lock Out (UVLO)

it will shut down all power rails and enter STANDBY mode. Shut down follows the reverse power-up sequence defined by the PWR_SEQx registers. Once a fault is detected, the PWR_GOOD and nINT pin are pulled low and the corresponding interrupt bit is set in the interrupt register.

Whenver the TPS65180/TPS65181 and TPS65180B/TPS65181B encounter under voltage on VNEG (VNEG_UV), VPOS (VPOS_UV), VEE (VEE_UV) or VDDH (VDDH_UV) it will shut down the corresponding rail (plus any dependent rail) only and remain in ACTIVE mode, allowing the DCDC converters to remain up. Again, the PWR_GOOD and nINT pins will be pulled low and the corresponding interrupt bit will be set.

TPS65180/TPS65180B FAULT HANDLING

Once a fault is detected the TPS65180/TPS65180B sets the appropriate interrupt flags in the INT_STATUS1 and INT_STATUS2 registers and pulls INT pin low to signal an interrupt to the host processor. None of the power rails can be re-enabled before the host has read the INT_STATUSx bits and the fault has been removed. As the PWRx inputs are edge sensitive, the host must also toggle the PWRx pins to re-enable the rails through GPIO control, i.e. it must bring the PWRx pins low before asserting them again.

TPS65181/TPS65181B FAULT HANDLING

The TPS65181/TPS65181does not require the host processor to access the INT_STATUS registers before re-enabling the output rails. Rails can be re-enabled as soon as the fault condition has been removed. Again, as the PWRx inputs are edge sensitive, the host must also toggle the PWRx pins to re-enable the rails through GPIO control, i.e. it must bring the PWRx pins low before asserting them again.

POWER GOOD PIN

The power good pin (PWR_GOOD) is an open drain output that is pulled high when all four power rails (CP1, CP2, LDO1, LDO2) are in regulation and is pulled low if any of the rails encounters a fault. PWR_GOOD remains low if one of the rails is not enabled by the host and only after all rails are in regulation PWR_GOOD is released to HiZ state (pulled up by external resistor).

INTERRUPT PIN

The interrupt pin (nINT) is an open drain output that is pulled low whenever one or more of the INT_STATUS1 or INT_STATUS2 bits are set. The nINT pin is released (returns to HiZ state) and fault bits are cleared once the register with the set bit has been read by the host. If the fault persists, the INT_pin will be pulled low again after a maximum of 32 µs.

Interrupt events can be masked by re-setting the corresponding enable bit in the INT_ENABLE1 and INT_ENABLE2 register, i.e. the user can determine which events cause the nINT pin to be pulled low. The status of the enable bits affects the nINT pin only and has no effect on any of the protection and monitoring circuits or the INT_STATUSx bits themselves.

Note that persisting fault conditions such as thermal shutdown can cause the nINT pin to be pulled low for an extended period of time which can keep the host in a loop trying to resolve the interrupt. If this behavior is not desired, set the corresponding mask bit after receiving the interrupt and keep polling the INT_STATUSx register to see when the fault condition has disappeared. After the fault is resolved, unmask the interrupt bit again.

PANEL TEMPERATURE MONITORING

The TPS65180/TPS65181 and TPS65180B/TPS65181B provide circuitry to bias and measure an external negative temperature coefficient resistor (NTC) to monitor device temperature in a range from –10°C to 85°C with and accuracy of ±1°C from 0°C to 50°C. The TPS65180/TPS65180B requires the host to trigger the temperature acquisition through an I^2C command whereas the TPS65181/TPS65181B triggers the temperature acquisition automatically once every 60 s.

NTC BIAS CIRCUIT

Figure 5 below shows the block diagram of the NTC bias and measurement circuit. The NTC is biased from an internally generated 2.25-V reference voltage through an integrated 7.307-kΩ bias resistor. A 43-kΩ resistor is connected parallel to the NTC to linearize the temperature response curve. The circuit is designed to work with a nominal 10-kΩ NTC and achieves accuracy of ±1°C from 0°C to 50°C. The voltage drop across the NTC is digitized by a 10-bit SAR ADC and translated into an 8-bit two's complement by digital per Table 1.

Table 1. ADC Output Value vs Termperature

TEMPERATURE	TMST_VALUE[7:0]
< -10°C	1111 0110
-10°C	1111 0110
-9°C	1111 0111
...	...
-2°C	1111 1110
-1°C	1111 1111
0°C	0000 0000
1°C	0000 0001
2°C	0000 0010
...	...
25°C	0001 1001
...	
85°C	0101 0101
> 85°C	0101 0101

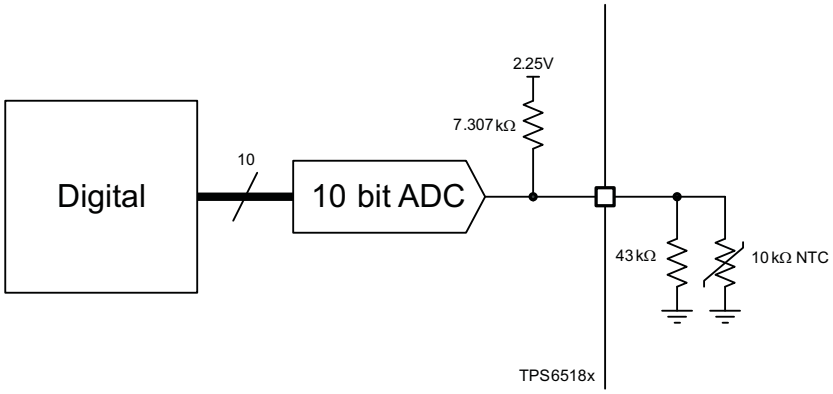


Figure 5. NTC Bias and Measurement Circuit

TPS65180/TPS65180B TEMPERATURE ACQUISITION

The TPS65180/TPS65180B requires the host to trigger the temperature acquisition before reading the temperature value from register TMST_VALUE. A standard temperature measurement involves the following steps:

1. The host sets the READ_THERM bit of the TMST_CONFIG register to 1. This enabled the NTC bias circuit and internal ADC.
2. The analog to digital conversion is automatically started after a fixed 250-µs delay. While the conversion is in progress the CONV_END bit of the TMST_CONFIG register is held low and returns to 1 after the conversion result is available.
3. After the conversion is complete the READ_THERM bit is automatically reset, the EOC bit of the INT_STATUS2 register is set, and the interrupt pin (nINT) is pulled low.
4. The host services the interrupt by reading the INT_STATUS2 register. This clears the interrupt pin (nINT pin returns high). The host sees the EOC bit set and knows that the temperature data is available in the TMST_VALUE register.
5. The host reads the temperature data from the TMST_VALUE register.

TPS65181/TPS65181B TEMPERATURE ACQUISITION

The TPS65181/TPS65181B triggers temperature acquisition once every 60s to reduce the number of required I^2C writes. The host or display timing controller can read the temperature at any time by accessing the TMST_VALUE register without having to set the READ_THERM bit first. However, the host can always trigger an

additional temperature reading the same way as for the TPS65180/TPS65180B. Please note that at the end of each temperature acquisition the EOC interrupt will be set and an interrupt will be issued. Although the interrupt is automatically cleared, the nINT pin will be pulled low for a short amount of time (6 µs). To avoid seeing the EOS interrupt every 60s it is recommended to mask the EOC interrupt by setting the EOC_EN bit of the INT_ENABLE2 register to 0.

OVER TEMPERATURE REPORTING

The user has the option of setting HOT and COOL (not HOT) temperature thresholds as well as controlling interrupt behavior as the NTC exceeds HOT and cools down below COOL (not-HOT) threshold.

By default, TPS65180/TPS65181 and TPS65180B/TPS65181B compare the temperature conversion result to the HOT threshold after each conversion. If the NTC temperature is above the HOT threshold, the TMST_HOT bit in the INT_STATUS1 register is set to 1 and the interrupt pin (nINT) is pulled low. HOT temperature threshold is set by the host by writing to the TMST_OS register and the HOT interrupt can be disabled by setting the HOT_EN bit of the INT_ENABLE1 register to 0.

Once the device has detected that the NTC is above the HOT threshold it will compare subsequent temperature acquisitions against the COOL threshold and pull the interrupt pin low when the NTC temperature drops below the COOL threshold. However, the interrupt will be issued only if the host has unmasked the COOL interrupt by setting TMST_COOL_EN bit of INT_ENABLE1 register to 1. The COOL threshold is set by the host by writing to the TMST_HYST register.

To use the full functionality of the HOT/COOL interrupts the following actions are required:

1. The host sets the HOT and COOL (not HOT) thresholds by writing the TMST_OS and TMST_HYST registers.
2. (2) For TPS65180/TPS65180B only: The host sets the READ_THERM bit of the TMST_CONFIG register to ‘1’. This initiates the temperature acquisition.
3. TPS65180/TPS65181 and TPS65180B/TPS65181B compare the result against the TMST_OS threshold and will pull the nINT pin low if the NTC temperature exceeds the HOT threshold.
4. If the TPS65180/TPS65181 and TPS65180B/TPS65181B report a HOT condition, the host unmasks the TMST_COOL_EN bit by setting it to 1 (INT_ENABLE1 register).
5. The host initiates a new temperature conversion by setting the READ_THERM bit of the TMST_CONFIG register to 1. If the new temperature is still above the HOT threshold, a new HOT interrupt will be issued. If the temperature is below HOT but above COOL threshold, no interrupt is issued (except for EOC which is issued at the end of each conversion). If the temperature is below COOL threshold, a COOL interrupt is issued.
6. After the temperature drops below the COOL threshold the host should set the TMST_COOL_EN bit in the INT_ENABLE1 register to 0 to mask additional COOL interrupts after subsequent temperature acquisitions.

OVER-TEMPERATURE FAULT QUEUING

The user can specify the number of consecutive HOT temperature reads required to issue a HOT interrupt. The user can set the FAULT_QUE[1:0] bits of the TMST_CONFIG register to specify 1, 2, 4, or 6 consecutive reads that all must be above the HOT threshold before a HOT interrupt is issued. The fault queue is reset each time the acquired temperature drops below the HOT threshold and can also be reset by the host by setting the FAULT_QUE_CLR bit 1. Only if the specified number of readings have been detected which all need to be above the HOT threshold, a HOT interrupt is issued. This function is useful to reduce noise in the temperature measurements.

TPS65181/TPS65181B TEMPERATURE SENSOR

The TPS65181/TPS65181B automates the temperature monitoring process and is specifically designed to operate in multi-host systems where one of the I^2C hosts, e.g. the display controller, has limited I^2C capability. Standard I^2C protocol requires the following steps to read data from a register:

1. Send device and register address, R/nW bit set low (write command).
2. Send device address, R/nW set high (read command).
3. The slave will respond with data from the specified register address.

Some display controllers support I^2C read commands only and need to access the temperature data from the

TPS65181/TPS65181B TMST_VALUE register. To support these systems the TPS65181/TPS65181B automatically triggers temperature acquisition every 60s (for other acquisition intervals contact the factory) and stores the result in TMST_VALUE register. With the FIX_RD_PTR bit in the FIX_RD_POINTER register set to 1 the device will respond to any I^2C read command with data from the TMST_VALUE register. No write command with the register address is required and address auto increment feature is disabled in this mode. Therefore reading the temperature data is reduced to two steps:

1. Send device address, R/nW set high (read command).
2. Read the data from the slave. The slave will respond with data from TMST_VALUE register address.

Write functionality is not affected by the FIX_RD_PTR bit and the main controller in the system maintains full control of the PMIC. Interrupts and error flags are issued and need to be handled the same way as for the TPS65180/TPS65180B with two exceptions:

1. The FIX_RD_PTR bit in the FIX_RD_POINTER register needs to be set to 0 before the main controller can read any register different from the TMST_VALUE register.
2. Thermal shutdown (TSD), positive boost under voltage (VB_UV), inverting buck-boost under voltage (VN_UV), and input under voltage lock out (UVLO) interrupt bits do not have to be cleared before output rails can be re-enabled.

At system power-up the main processor sets up the PMIC by accessing the I^2C registers and setting the control parameters as needed. When the system is setup correctly the main controller sets the FIX_READ_POINTER bit and the display controller can start accessing the temperature information. During normal operation the main controller can write to the PMIC at any time but before it can read access registers the FIX_READ_POINTER bit must be written 0.

The temperature range and representation of the temperature data is the same between the TPS65180/TPS65180B and TPS65181/TPS65181B.

THE FIX_RD_PTR BIT

The TPS65181/TPS65181B supports a special I^2C mode making it compatible with the EPSON Broadsheet S1D13521 timing controller. Standard I^2C protocol requires the following steps to read data from a register:

1. Send device slave address, R/nW bit set low (write command)
2. Send register address
3. Send device slave address, R/nW set high (read command)
4. The slave will respond with data from the specified register address.

The EPSON Broadsheet S1D13521 controller does not support I^2C writes nor I^2C reads from addressed registers (step 1. and 2. above) but needs to access the temperature data from the TPS65181/TPS65181B's TMST_VALUE register. To support Broadsheet based systems, the TPS65181/TPS65181B automatically triggers temperature acquisition every 60s and stores the result in TMST_VALUE register. With the FIX_RD_PTR bit in the FIX_RD_POINTER register set to 1 the device will respond to any I^2C read command with data from the TMST_VALUE register. No write command with the register address is required and address auto increment feature is disabled in this mode. Therefore reading the temperature data is reduced to two steps:

1. Send device address, R/nW set high (read command)
2. Read the data from the slave. The slave will respond with data from TMST_VALUE register address.

Write functionality is not affected by the FIX_RD_PTR bit and the main controller in the system maintains full control of the PMIC. Interrupts and error flags are issued and need to be handled the same way as for the TPS65180/TPS65180B with two exceptions:

1. The FIX_RD_PTR bit in the FIX_RD_POINTER register needs to be set to 0 before the main controller can read any register different from the TMST_VALUE register.
2. Thermal Shutdown (TSD), positive boost Under Voltage (VB_UV), inverting buck-boost Under Voltage (VN_UV), and input Under Voltage Lock Out (UVLO) interrupt bits do not have to be cleared before output rails can be re-enabled.

At system power-up the main processor sets up the PMIC by accessing the I²C registers and setting the control parameters as needed. When the system is setup correctly the main controller sets the FIX_READ_POINTER bit and the display controller can start accessing the temperature information. During normal operation the main controller can write to the PMIC at any time but before it can read access registers the FIX_READ_POINTER bit must be written 0.

I²C BUS OPERATION

The TPS65180/TPS65181 and TPS65180B/TPS65181B host a slave I²C interface that supports data rates up to 400 kbit/s and auto-increment addressing and is compliant to I²C standard 3.0.

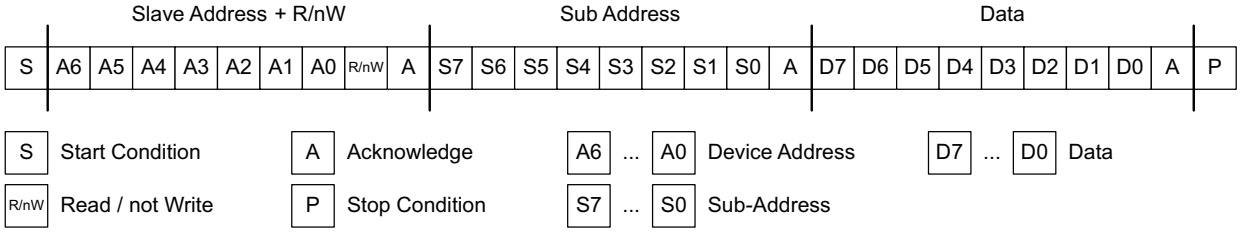


Figure 6. Subaddress in I²C Transmission

Start – Start condition
G(3:0) – Group ID: Address fixed at 1001.
A(2:0) – Device Address: Address fixed at 000.
R/nW – Read / not Write Select Bit
ACK – Acknowledge
S(7:0) – Subaddress: defined per register map.
D(7:0) – Data; Data to be loaded into the device.
Stop – Stop condition

The I²C Bus is a communications link between a controller and a series of slave terminals. The link is established using a two-wired bus consisting of a serial clock signal (SCL) and a serial data signal (SDA). The serial clock is sourced from the controller in all cases where the serial data line is bi-directional for data communication between the controller and the slave terminals. Each device has an open Drain output to transmit data on the serial data line. An external pull-up resistor must be placed on the serial data line to pull the drain output high during data transmission.

Data transmission is initiated with a start bit from the controller as shown in Figure 8. The start condition is recognized when the SDA line transitions from high to low during the high portion of the SCL signal. Upon reception of a start bit, the device will receive serial data on the SDA input and check for valid address and control information. If the appropriate group and address bits are set for the device, then the device will issue an acknowledge pulse and prepare the receive subaddress data. Subaddress data is decoded and responded to as per the Register Map section of this document. Data transmission is completed by either the reception of a stop condition or the reception of the data word sent to the device. A stop condition is recognized as a low to high transition of the SDA input during the high portion of the SCL signal. All other transitions of the SDA line must occur during the low portion of the SCL signal. An acknowledge is issued after the reception of valid address, sub-address and data words. The I²C interface will auto-sequence through register addresses, so that multiple data words can be sent for a given I²C transmission. Reference Figure 8. Please note that auto-increment is not supported when the FIX_RD_PTR bit is set (TPS65181/TPS65181B only).

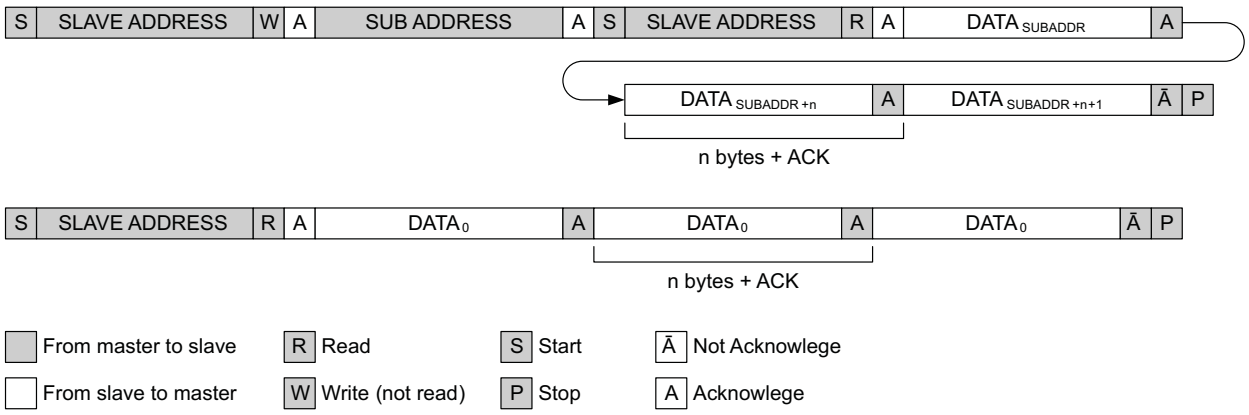


Figure 7. TOP: Standard I²C READ data transmission with address auto-increment. Bottom: I²C READ data transmission with FIX_RD_PTR bit set for EPSON Broadsheet support. Only address 0x00h can be read. FIX_RD_PTR bit has no impact on WRITE transaction.

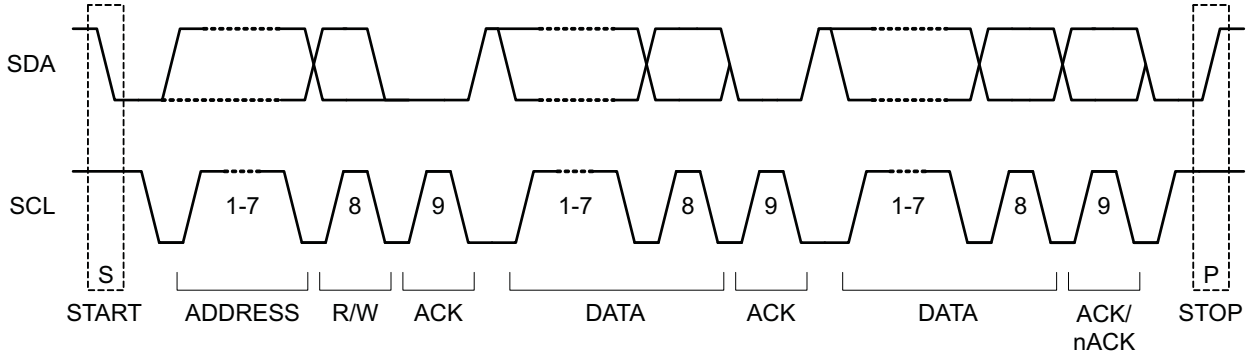


Figure 8. I²C Start/Stop/Acknowledge Protocol

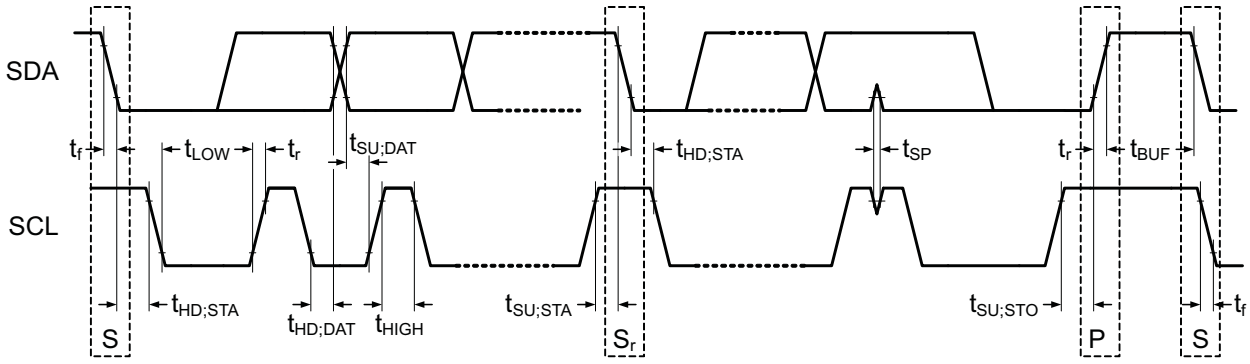


Figure 9. I²C Data Transmission Timing

DATA TRANSMISSION TIMING

V_{BAT} = 3.6 V ±5%, T_A = 25ºC, C_L = 100 pF (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{(SCL)}$	Serial clock frequency		100		400	KHz
$t_{HD;STA}$	Hold time (repeated) START condition. After this period, the first clock pulse is generated.	SCL = 100 KHz	4			µs
		SCL = 400 KHz	600			ns
t_{LOW}	LOW period of the SCL clock	SCL = 100 KHz	4.7			µs
		SCL = 400 KHz	1.3			
t_{HIGH}	HIGH period of the SCL clock	SCL = 100 KHz	4			µs
		SCL = 400 KHz	600			ns
$t_{SU;STA}$	Set-up time for a repeated START condition	SCL = 100 KHz	4.7			µs
		SCL = 400 KHz	600			ns
$t_{HD;DAT}$	Data hold time	SCL = 100 KHz	0		3.45	µs
		SCL = 400 KHz	0		900	ns
$t_{SU;DAT}$	Data set-up time	SCL = 100 KHz	250			ns
		SCL = 400 KHz	100			
t_r	Rise time of both SDA and SCL signals	SCL = 100 KHz			1000	ns
		SCL = 400 KHz			300	
t_f	Fall time of both SDA and SCL signals	SCL = 100 KHz			300	ns
		SCL = 400 KHz			300	
$t_{SU;STO}$	Set-up time for STOP condition	SCL = 100 KHz	4			µs
		SCL = 400 KHz	600			ns
t_{BUF}	Bus Free Time Between Stop and Start Condition	SCL = 100 KHz	4.7			µs
		SCL = 400 KHz	1.3			
t_{SP}	Pulse width of spikes which mst be suppressed by the input filter	SCL = 100 KHz	n/a		n/a	ns
		SCL = 400 KHz	0		50	
C_b	Capacitive load for each bus line	SCL = 100 KHz			400	pF
		SCL = 400 KHz			400	

REGISTER ADDRESS MAP

REGISTER	ADDRESS (HEX)	NAME	DEFAULT VALUE	DESCRIPTION
0	0x00	TMST_VALUE	N/A	Thermistor value read by ADC
1	0x01	ENABLE	0001 1111	Enable/disable bits for regulators
2	0x02	VP_ADJUST	0010 0011	Voltage settings for VPOS, VDDH
3	0x03	VN_ADJUST	1010 0011	Voltage settings for VNEG, VEE
4	0x04	VCOM_ADJUST	0111 0100	Voltage settings for VCOM
5	0x05	INT_ENABLE1	0111 0100	Interrupt enable group1
6	0x06	INT_ENABLE2	1111 1011	Interrupt enable group2
7	0x07	INT_STATUS1	0xxx xx00	Interrupt status group1
8	0x08	INT_STATUS2	xxxx x0xx	Interrupt status group2
9	0x09	PWR_SEQ0	1110 0100	Power up sequence
10	0x0A	PWR_SEQ1	0010 0010	DLY0, DLY1 time set
11	0x0B	PWR_SEQ2	0010 0010	DLY2, DLY3 time set
12	0x0C	TMST_CONFIG	0010 0000	Thermistor configuration
13	0x0D	TMST_OS	0011 0010	Thermistor hot temp set
14	0x0E	TMST_HYST	0010 1101	Thermistor cool temp set
15	0x0F	PG_STATUS	0000 0000	Power good status each rails
16	0x10	REVID	0100 0001	Device revision ID information
17	0x11	FIX_READ_POINTER	0000 0000	I^2C read pointer control

THERMISTOR READOUT (TMST_VALUE)

Address – 0x00h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	TMST_VALUE[7:0]							
READ/WRITE	R	R	R	R	R	R	R	R
RESET VALUE	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A

FIELD NAME	BIT DEFINITION
TMST_VALUE[7:0]	Temperature read-out 1111 0110 – < -10°C 1111 0110 – -10°C 1111 0111 – -9°C ... 1111 1110 – -2°C 1111 1111 – -1 °C 0000 0000 – 0 °C 0000 0001 – 1°C 0000 0010 – 2°C ... 0001 1001 – 25°C ... 0101 0101 – 85°C 0101 0101 – > 85°C

ENABLE (ENABLE)

Address – 0x01h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	ACTIVE	STANDBY	V3P3_SW_EN	VCOM_EN	VDDH_EN	VPOS_EN	VEE_EN	VNEG_EN
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	0	0	0	1	1	1	1	1

FIELD NAME	BIT DEFINITION(1)
ACTIVE	STANDBY to ACTIVE transition bit 1 – Transition from STANDBY to ACTIVE mode. Rails power up as defined by PWR_SEQx registers. 0 – No effect NOTE: After transition bit is cleared automatically.
STANDBY	ACTIVE to STANDBY transition bit 1 – Transition from ACTIVE to STANDBY mode. Rails power down as defined by PWR_SEQx registers. 0 – No effect NOTE: After transition bit is cleared automatically. STANDBY bit has priority over AVTIVE.
V3P3_SW_EN	VIN3P3 to V3P3 switch enable 1 – Switch is ON 0 – Switch id OFF
VCOM_EN	VCOM buffer enable 1 – Enabled 0 – Disabled

(1) Enable/disable bits for regulators are AND'd with PWRx signals.

FIELD NAME	BIT DEFINITION(1)
VDDH_EN	VDDH charge pump enable 1 – Enabled 0 – Disabled
VPOS_EN	VPOS LDO regulator enable 1 – Enabled 0 – Disabled NOTE: VPOS cannot be enabled before VNEG is enabled.
VEE_EN	VEE charge pump enable 1 – Enabled 0 – Disabled
VNEG_EN	VNEG LDO regulator enable 1 – Enabled 0 – Disabled NOTE: When VNEG is disabled VPOS will also be disabled.

POSITIVE VOLTAGE RAIL ADJUSTMENT (VP_ADJUST)

Address – 0x02h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	Not used	VDDH_SET[2:0]			not used	VPOS_SET[2:0]		
READ/WRITE	R	R/W	R/W	R/W	R	R/W	R/W	R/W
RESET VALUE	0	0	1	0	0	0	1	1

FIELD NAME	BIT DEFINITION(1)
Not used	N/A
VDDH_SET[2:0]	VDDH voltage setting 000 – VDDH increase by 10% 001 – VDDH increase by 5% 010 – Nominal 011 – VDDH decrease by 5% 100 – VDDH decrease by 10% 101 – Reserved 110 – Reserved 111 – Reserved
Not used	N/A
VPOS_SET[2:0]	VPOS voltage setting 000 : |VNEG| - 0.75 V 001 : |VNEG| - 0.5 V 010 : |VNEG| - 0.25 V 011 : |VNEG| 100 : |VNEG| + 0.25 V 101 : |VNEG| + 0.5 V 110 : |VNEG| + 0.75 V 111 – Reserved NOTE: For proper tracking of the VPOS and VNEG supply these bits must remain set at their default value of 011b. VPOS will track VNEG automatically when VNEG_SET[2:0] bits of VN_ADJUST register are changed.

(1) VDDH will be decreased from set value defined by resistor divider. Decreased VDDH value should be within spec range.

NEGATIVE VOLTAGE RAIL ADJUSTMENT (VN_ADJUST)

Address – 0x03h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	VCOM_ADJ	VEE_SET[2:0]			Not used	VNEG_SET[2:0]		
READ/WRITE	R/W	R/W	R/W	R/W	R	R/W	R/W	R/W
RESET VALUE	1(1)	0	1	0	0	0	1	1

(1) TPS65180/TPS65180B: Bit defaults to 1; TPS65181/TPS65181B: Bit defaults to 0

FIELD NAME	BIT DEFINITION
VCOM_ADJ	VCOM output adjustment method 0 – VCOM_XADJ pin 1 – I^2C interface
VEE_SET[2:0](1)	VDDH voltage setting 000 – VEE decrease by 10% 001 – VEE decrease by 5% 010 – Nominal 011 – VEE increase by 5% 100 – VEE increase by 10% 101 – Reserved 110 – Reserved 111 – Reserved
not used	N/A
VNEG_SET[2:0]	VNEG voltage setting 000 – -15.75 V 001 – -15.50 V 010 – -15.25 V 011 – -15.00 V 100 – -14.75 V 101 – -14.50 V 110 – -14.25 V 111 – Reserved

(1) VEE will be decreased from set value defined by resistor divider. Decreased VEE value should be within spec range.

VCOM ADJUSTMENT (VCOM_ADJUST)

Address – 0x04h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	VCOM_SET[7:0]							
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	0	1	1	1	0	1	0	0

FIELD NAME	BIT DEFINITION
VCOM_SET[7:0]	VCOM voltage adjustment 0000 0000 – 0 V 0000 0001 – 11 mV 0000 0010 – 22 mV ... 0111 0011 – 1239 mV 0111 0100 – 1250 mV 0111 0101 – 1261 mV ... 1111 1111 – 2750 mV NOTE: step size is rounded to 11 mV. Theoretical step size is 2750 mV / 255 mV = 10.78 mV. Parametric performance is guranteed from -0.3 V to -2.5 V only.

INTERRUPT ENABLE 1 (INT_ENABLE1)

Address – 0x05h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	Not used	TSD_EN	HOT_EN	TMST_HOT_EN	TMST_COOL_EN	UVLO_EN	Not used	Not used
READ/WRITE	R	R/W	R/W	R/W	R/W	R/W	R	R
RESET VALUE	0	1	1	1	0	1	0	0

FIELD NAME	BIT DEFINITION
Not used	N/A
TSD_EN	Thermal shutdown interrupt enable 1 – Enabled 0 – Disabled
HOT_EN	Thermal shutdown early warning enable 1 – Enabled 0 – Disabled
TMST_HOT_EN	Thermistor hot warning enable 1 – Enabled 0 – Disabled
TMST_COOL_EN	Thermistor hot escape interrupt enable 1 – Enabled 0 – Disabled
UVLO_EN	VIN under voltage detect interrupt enable 1 – Enabled 0 – Disabled
Not used	N/A
Not used	N/A

INTERRUPT ENABLE 2 (INT_ENABLE2)

Address – 0x06h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	VB_UV_EN	VDDH_UV_EN	VN_UV_EN	VPOS_UV_EN	VEE_UV_EN	not used	VNEG_UV_EN	EOC_EN
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R	R/W	R/W
RESET VALUE	1	1	1	1	1	0	1	1

FIELD NAME	BIT DEFINITION
VB_UV_EN	Positive boost converter under voltage detect interrupt enable 1 – Enabled 0 – Disabled
VDDH_UV_EN	VDDH under voltage detect interrupt enable 1 – Enabled 0 – Disabled
VN_UV_EN	Inverting buck-boost converter under voltage detect interrupt enable 1 – Enabled 0 – Disabled
VPOS_UV_EN	VPOS under voltage detect interrupt enable 1 – Enabled 0 – Disabled
VEE_UV_EN	VEE under voltage detect interrupt enable 1 – Enabled 0 – Disabled
not used	N/A
VNEG_UV_EN	VNEG under voltage detect interrupt enable 1 – Enabled 0 – Disabled
EOC_EN	ADC end of conversion interrupt enable 1 – Enabled 0 – Disabled

INTERRUPT INT_STATUS1 (INT_STATUS1)

Address – 0x07h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	Not used	TSDN	HOT	TMST_HOT	TMST_COOL	UVLO	Not used	Not used
READ/WRITE	R	R	R	R	R	R	R	R
RESET VALUE	0	N/A	N/A	N/A	N/A	N/A	0	0

FIELD NAME	BIT DEFINITION
Not used	N/A
TSD	Thermal shutdown interrupt
HOT	Thermal shutdown early warning
TMST_HOT	Thermistor hot warning
TMST_COOL	Thermistor hot escape interrupt
UVLO	VIN under voltage detect interrupt
Not used	N/A
Not used	N/A

INTERRUPT STATUS 2 (INT_STATUS2)

Address – 0x08h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	VB_UV	VDDH_UV	VN_UV	VPOS_UV	VEE_UV	Not used	VNEG_UV	EOC
READ/WRITE	R	R	R	R	R	R	R	R
RESET VALUE	N/A	N/A	N/A	N/A	N/A	0	N/A	N/A

FIELD NAME	BIT DEFINITION(1)
VB_UV	Positive boost converter under voltage detect interrupt
VDDH_UV	VDDH under voltage detect interrupt
VN_UV	Inverting buck-boost converter under voltage detect interrupt
VPOS_UV	VPOS under voltage detect interrupt
VEE_UV	VEE under Voltage detect interrupt
not used	N/A
VNEG_UV	VNEG under voltage detect interrupt
EOC	ADC end of conversion interrupt

(1) Under voltage detect bit is set if the corresponding rail does not come up 5 ms after it is enabled except for DCDC1 and 2 which are set 10 ms after they are enabled.

POWER SEQUENCE REGISTER 0 (PWR_SEQ0)

Address – 0x09h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	VDDH_SEQ[1:0]		VPOS_SEQ[1:0]		VEE_SEQ[1:0]		VNEG_SEQ[1:0]	
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	1	1	1	0	0	1	0	0

FIELD NAME	BIT DEFINITION(1)
VDDH_SEQ[1:0]	VDDH power-up/down order 00 – Power-up/down on STROBE1 01 – Power-up/down on STROBE2 10 – Power-up/down on STROBE3 11 – Power-up/down on STROBE4
VPOS_SEQ[1:0]	VPOS power-up/down order 00 – Power-up/down on STROBE1 01 – Power-up/down on STROBE2 10 – Power-up/down on STROBE3 11 – Ppower-up/down on STROBE4
VEE_SEQ[1:0]	VEE power-up/down order 00 – Power-up/down on STROBE1 01 – Power-up/down on STROBE2 10 – Power-up/down on STROBE3 11 – Power-up/down on STROBE4
VNEG_SEQ[1:0]	VNEG power-up/down order 00 – Power-up/down on STROBE1 01 – Power-up/down on STROBE2 10 – Power-up/down on STROBE3 11 – Power-up/down on STROBE4

(1) Power-down sequence follows the reverse order of power-up.

POWER SEQUENCE REGISTER 1 (PWR_SEQ1)

Address – 0x0Ah

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	DLY1[3:0]				DLY0[3:0]			
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	0	0	1	0	0	0	1	0

FIELD NAME	BIT DEFINITION
DLY1[3:0]	DLY1 delay time set; defines the delay time from STROBE1 to STROBE2 during power-up and from STROBE2 to STROBE1 during power-down. 0000 – 0 ms 0001 – 1 ms 0010 – 2 ms 0011 – 3 ms ... 1110 – 14 ms 1111 – 15 ms
DLY0[3:0]	DLY0 delay time set; defines the delay time from WAKEUP high to STROBE1 during power-up and from WAKEUP low to STROBE4 during power-down. 0000 – 0 ms 0001 – 1 ms 0010 – 2 ms 0011 – 3 ms ... 1110 – 14 ms 1111 – 15 ms

POWER SEQUENCE REGISTER 2 (PWR_SEQ2)

Address – 0x0Bh

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	DLY3[3:0]				DLY2[3:0]			
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	0	0	1	0	0	0	1	0

FIELD NAME	BIT DEFINITION
DLY3[3:0]	DLY3 delay time set; defines the delay time from STROBE3 to STROBE4 during power-up and from STROBE4 to STROBE3 during power-down. 0000 – 0 ms 0001 – 1 ms 0010 – 2 ms 0011 – 3 ms ... 1110 – 14 ms 1111 – 15 ms
DLY2[3:0]	DLY2 delay time set; defines the delay time from STROBE2 to STROBE3 during power-up and from STROBE3 to STROBE2 during power-down. 0000 – 0 ms 0001 – 1 ms 0010 – 2 ms 0011 – 3 ms ... 1110 – 14 ms 1111 – 15 ms

THERMISTOR CONFIGURATION REGISTER (TMST_CONFIG)

Address – 0x0Ch

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	READ_ THERM	Not used	CONV_END	FAULT_QUE [1:0]		FAULT_QUE _CLR	Not used	Not used
READ/WRITE	R/W	R	R	R/W	R/W	R/W	R	R
RESET VALUE	0	0	1	0	0	0	0	0

FIELD NAME	BIT DEFINITION
READ_THERM	Read thermistor value 1 – Initiates temperature acquisition 0 – No effect NOTE: bit is self-cleared after acquisition is completed
Not used	N/A
CONV_END	ADC conversion done flag 1 – Conversion is finished 0 – Conversion is not finished
FAULT_QUE [1:0]	Number of faults to detect before TMST_HOT interrupt is asserted 00 – 1 time 01 – 2 times 10 – 4 times 11 – 6 times
FAULT_QUE_CLR	Fault counter clear 1 – Clears fault counter 0 – Fault counter is cleared automatically if thermistor reading is less than TMST_HOT_SET[7:0]
Not used	N/A
Not used	N/A

THERMISTOR HOT THRESHOLD (TMST_OS)

Address – 0x0Dh

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	TMST_HOT_SET[7:0]							
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	0	0	1	1	0	0	1	0

FIELD NAME	BIT DEFINITION
TMST_HOT_SET[7:0]	Defined the thermistor HOT threshold 1000 0000 – Reserved ... 1111 0101 – Reserved 1111 0110 – -10°C 1111 0111 – -9°C ... 1111 1110 – -2°C 1111 1111 – -1°C 0000 0000 – 0°C 0000 0001 – 1°C 0000 0010 – 2°C ... 0001 1001 – 25°C ... 0011 0010 – 50°C ... 0101 0101 – 85°C 0101 0110 – Reserved ... 0111 1111 – Reserved

THERMISTOR COOL THRESHOLD (TMST_HYST)

Address – 0x0Eh

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	TMST_COOL_SET[7:0]							
READ/WRITE	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET VALUE	0	0	1	0	1	1	0	1

FIELD NAME	BIT DEFINITION
TMST_HOT_SET[7:0]	Defined the thermistor HOT threshold 1000 0000 – Reserved ... 1111 0101 – Reserved 1111 0110 – -10°C 1111 0111 – -9°C ... 1111 1110 – -2°C 1111 1111 – -1°C 0000 0000 – 0°C 0000 0001 – 1°C 0000 0010 – 2°C ... 0001 1001 – 25°C ... 0010 1101 – 45°C ... 0101 0101 – 85°C 0101 0110 – Reserved ... 0111 1111 – Reserved

POWER GOOD STATUS (PG_STATUS)

Address – 0x0Fh

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	VB_PG	VDDH_PG	VN_PG	VPOS_PG	VEE_PG	Not used	VNEG_PG	Not used
READ/WRITE	R	R	R	R	R	R	R	R
RESET VALUE	0	0	0	0	0	0	0	0

FIELD NAME	BIT DEFINITION
VB_PG	Positive boost converter power good
VDDH_PG	VDDH power good
VN_PG	Inverting buck-boost power good
VPOS_PG	VPOS power good
VEE_PG	VEE power good
not used	N/A
VNEG_PG	VNEG power good
not used	N/A

REVISION AND VERSION CONTROL (REVID)

Address – 0x10h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	REVID[7:0]							
READ/WRITE	R	R	R	R	R	R	R	R
RESET VALUE	0	1	1	1	0	0	0	0

FIELD NAME	BIT DEFINITION
REVID [7:0]	0101 0000 - TPS65180 1p1 0110 0000 - TPS65180 1p2 0111 0000 - TPS65180B (TPS65180 1p3) 1000 0000 - TPS65180B (TPS65180 1p4) 0101 0001 - TPS65181 1p1 0110 0001 - TPS65181 1p2 0111 0001 - TPS65181B (TPS65181 1p3) 1000 0001 - TPS65181B (TPS65181 1p4)

I^2C READ POINTER CONTROL (FIX_READ_POINTER) (TPS65181/TPS65181B ONLY)

Address – 0x11h

DATA BIT	D7	D6	D5	D4	D3	D2	D1	D0
FIELD NAME	Not used	Not used	Not used	Not used	Not used	Not used	Not used	FIX_RD_PTR
READ/WRITE	R	R	R	R	R	R	R	R/W
RESET VALUE	0	0	0	0	0	0	0	0

FIELD NAME	BIT DEFINITION
Not used	N/A
Not used	N/A
Not used	N/A
Not used	N/A
Not used	N/A
Not used	N/A
Not used	N/A
FIX_RD_PTR	I^2C read pointer control 1 – Read pointer is fixed to 0x00 0 – read pointer is controlled through I^2C

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TPS65180BRGZR	ACTIVE	VQFN	RGZ	48	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65180B	Samples
TPS65180BRGZT	ACTIVE	VQFN	RGZ	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65180B	Samples
TPS65180RGZR	NRND	VQFN	RGZ	48	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65180	
TPS65180RGZT	NRND	VQFN	RGZ	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65180	
TPS65181BRGZR	ACTIVE	VQFN	RGZ	48	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65181B	Samples
TPS65181BRGZT	ACTIVE	VQFN	RGZ	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65181B	Samples
TPS65181RGZR	NRND	VQFN	RGZ	48	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65181	
TPS65181RGZT	NRND	VQFN	RGZ	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-10 to 85	E INK TPS65181	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

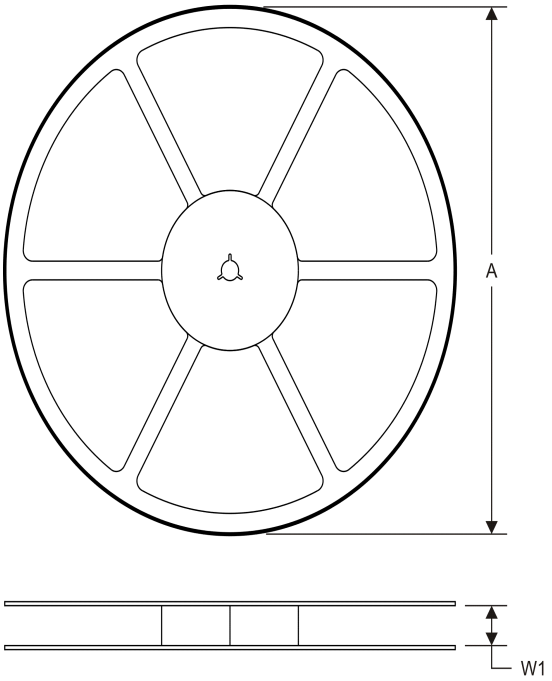
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

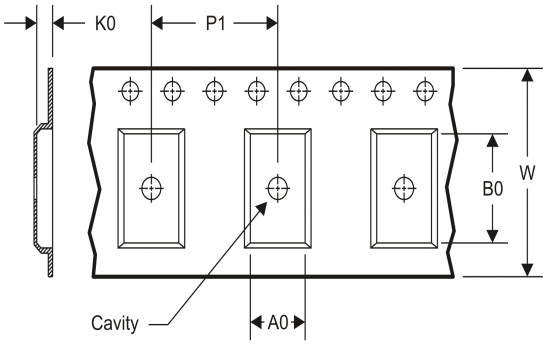
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



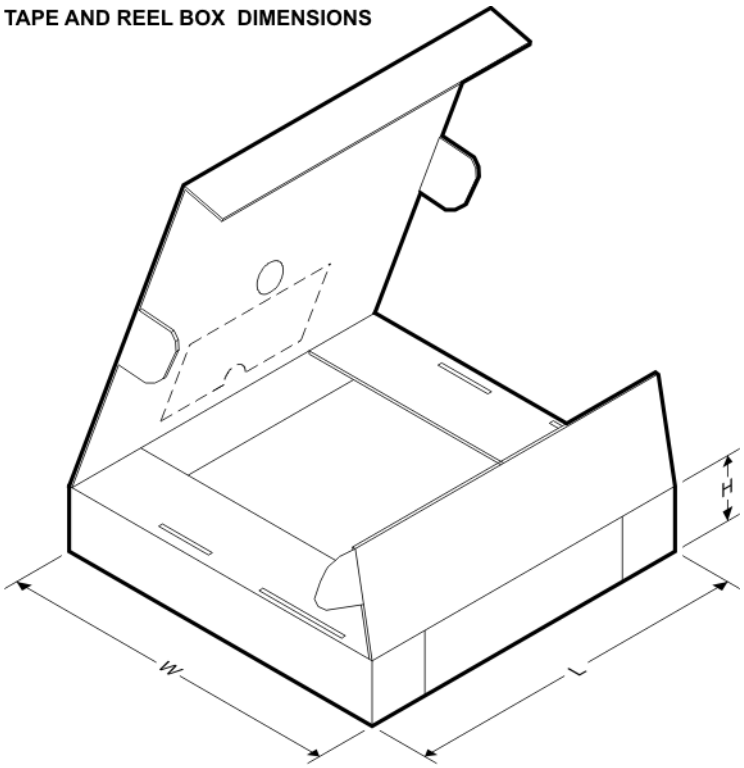
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS65180BRGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65180BRGZT	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65180RGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65180RGZT	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65181BRGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65181BRGZT	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65181RGZR	VQFN	RGZ	48	2500	330.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2
TPS65181RGZT	VQFN	RGZ	48	250	180.0	16.4	7.3	7.3	1.5	12.0	16.0	Q2

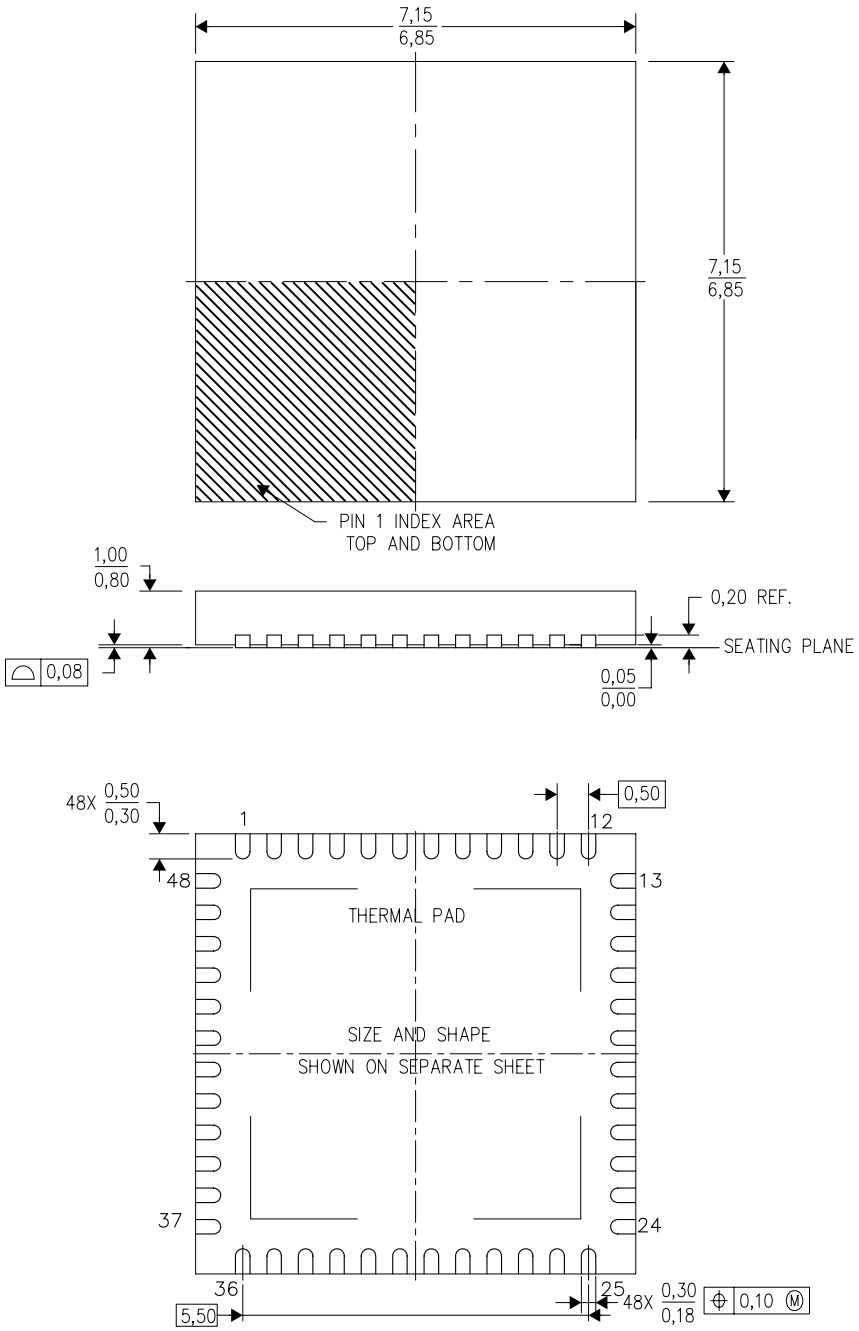
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS65180BRGZR	VQFN	RGZ	48	2500	367.0	367.0	38.0
TPS65180BRGZT	VQFN	RGZ	48	250	210.0	185.0	35.0
TPS65180RGZR	VQFN	RGZ	48	2500	367.0	367.0	38.0
TPS65180RGZT	VQFN	RGZ	48	250	210.0	185.0	35.0
TPS65181BRGZR	VQFN	RGZ	48	2500	367.0	367.0	38.0
TPS65181BRGZT	VQFN	RGZ	48	250	210.0	185.0	35.0
TPS65181RGZR	VQFN	RGZ	48	2500	367.0	367.0	38.0
TPS65181RGZT	VQFN	RGZ	48	250	210.0	185.0	35.0

RGZ (S–PVQFN–N48) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Quad Flatpack, No–leads (QFN) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Falls within JEDEC MO–220.

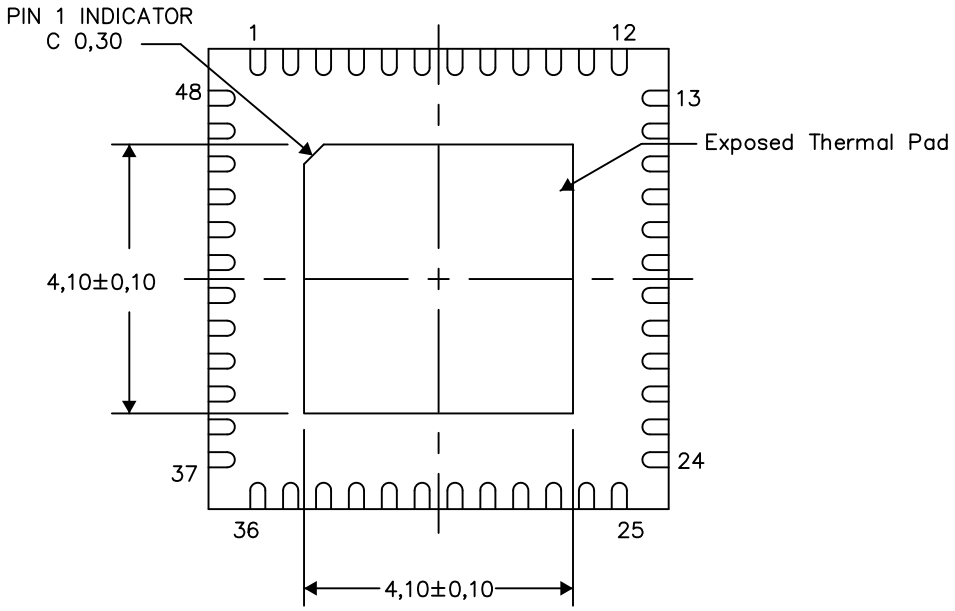
RGZ (S–PVQFN–N48) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



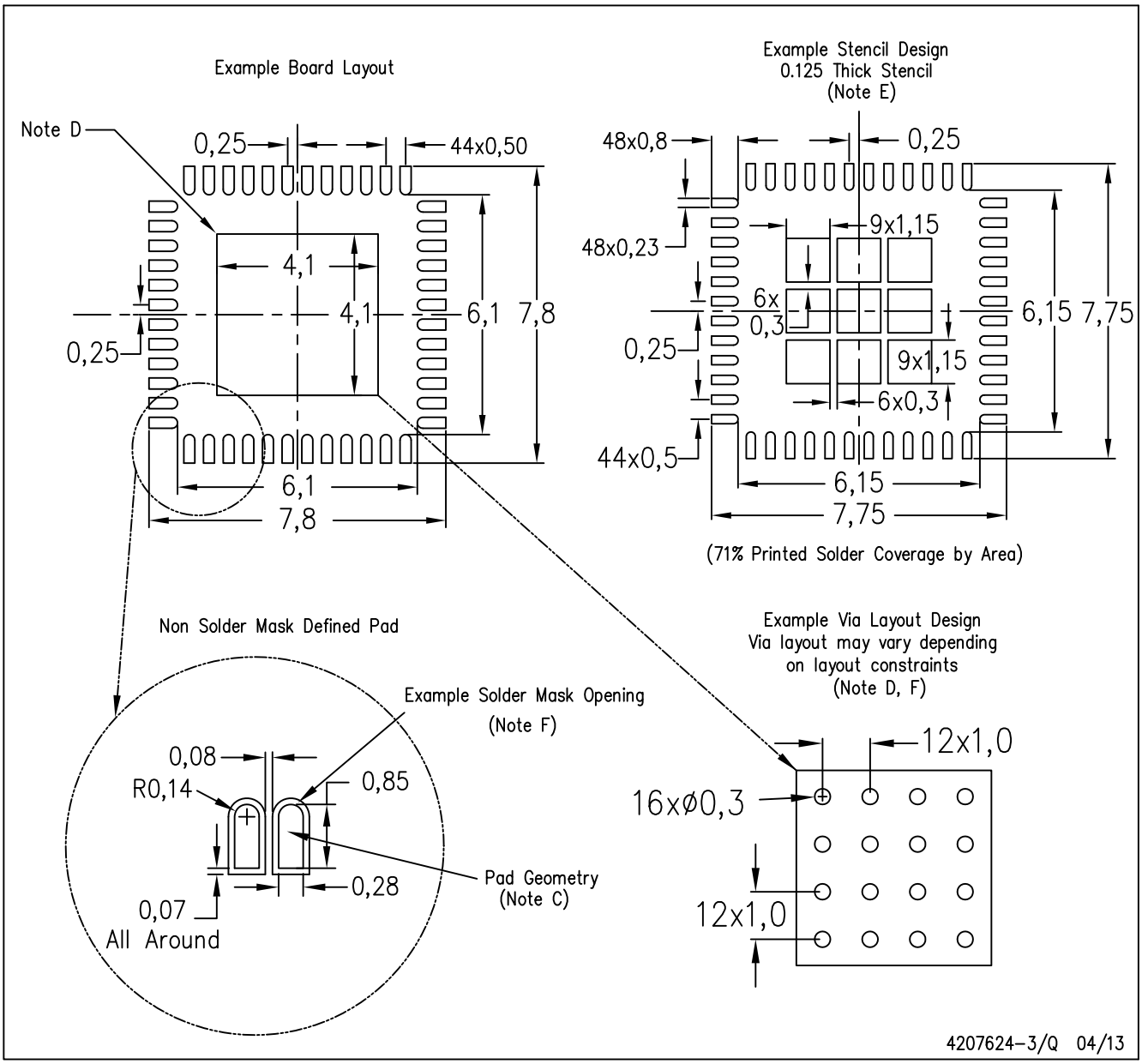
Bottom View

Exposed Thermal Pad Dimensions

4206354–3/U 04/13

NOTE: All linear dimensions are in millimeters

RGZ (S–PVQFN–N48) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http: //www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265